

M66 Hardware Design

GSM/GPRS Module Series

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About the Document

History

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1 Introduction

This document defines the M66 module and describes its hardware interface which are connected with the customer application and the air interface.

This document can help you quickly understand module interface specifications, electrical and mechanical details. Associated with application note and user guide, you can use M66 module to design and set up mobile applications easily.

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1.1. Safety Information

The following safety precautions must be observed during all phases of the operation, such as usage, service or repair of any cellular terminal or mobile incorporating M66 module. Manufacturers of the cellular terminal should send the following safety information to users and operating personnel and to incorporate these guidelines into all manuals supplied with the product. If not so, Quectel does not take on any liability for customer failure to comply with these precautions.



Full attention must be given to driving at all times in order to reduce the risk of an accident. Using a mobile while driving (even with a handsfree kit) cause distraction and can lead to an accident. You must comply with laws and regulations restricting the use of wireless devices while driving.



Switch off the cellular terminal or mobile before boarding an aircraft. Make sure it switched off. The operation of wireless appliances in an aircraft is forbidden to prevent interference with communication systems. Consult the airline staff about the use of wireless devices on boarding the aircraft, if your device offers a Airplane Mode which must be enabled prior to boarding an aircraft.



Switch off your wireless device when in hospitals or clinics or other health care facilities. These requests are desinged to prevent possible interference with sentitive medical equipment.



GSM cellular terminals or mobiles operate over radio frequency signal and cellular network and cannot be guaranteed to connect in all conditions, for example no mobile fee or an invalid SIM card. While you are in this condition and need emergent help, please remember using emergency call. In order to make or receive call, the cellular terminal or mobile must be switched on and in a service area with adequate cellular signal strength.



Your cellular terminal or mobile contains a transmitter and receiver. When it is ON , it receives and transmits radio frequency energy. RF interference can occur if it is used close to TV set, radio, computer or other electric equipment.



In locations with potentially explosive atmospheres, obey all posted signs to turn off wireless devices such as your phone or other cellular terminals. Areas with potentially exposable atmospheres including fuelling areas, below decks on boats, fuel or chemical transfer or storage facilities, areas where the air contains chemicals or particles such as grain, dust or metal powders.

2 Product Concept

2.1. General Description

M66 is a Quad-band GSM/GPRS engine that works at frequencies of GSM850MHz, GSM900MHz, DCS1800MHz and PCS1900MHz. The M66 features GPRS multi-slot class 12 and supports the GPRS coding schemes CS-1, CS-2, CS-3 and CS-4. For more details about GPRS multi-slot classes and coding schemes, please refer to the **Appendix B & C**.

With a tiny profile of 15.8mm × 17.7mm × 2.3mm, the module can meet almost all the requirements for M2M applications, including Vehicles and Personal Tracking, Security System, Wireless POS, Industrial PDA, Smart Metering, and Remote Maintenance& Control, etc.

M66 is an SMD type module with LCC package, which can be easily embedded into applications. It provides abundant hardware interfaces like PCM Interface.

Designed with power saving technique, the current consumption of M66 is as low as 1.3 mA in SLEEP mode when DRX is 5.

M66 is integrated with Internet service protocols, such as TCP/UDP, FTP and PPP. Extended AT commands have been developed for you to use these Internet service protocols easily.

M66 supports Bluetooth interface, It is fully compliant with Bluetooth specification 3.0.

The module fully complies with the RoHS directive of the European Union.

2.2. Key Features

The following table describes the detailed features of M66 module.

Table 1: Module Key Features

Feature	Implementation
Power Supply	Single supply voltage: 3.3V ~ 4.6V Typical supply voltage: 4V
Power Saving	Typical power consumption in SLEEP mode: 1.3 mA @DRX=5 1.2 mA @DRX=9
Frequency Bands	<ul style="list-style-type: none"> ● Quad-band: GSM850, GSM900, DCS1800, PCS1900. ● The module can search these frequency bands automatically ● The frequency bands can be set by AT command ● Compliant to GSM Phase 2/2+
GSM Class	Small MS
Transmitting Power	<ul style="list-style-type: none"> ● Class 4 (2W) at GSM850 and GSM900 ● Class 1 (1W) at DCS1800 and PCS1900
GPRS Connectivity	<ul style="list-style-type: none"> ● GPRS multi-slot class 12 (default) ● GPRS multi-slot class 1~12 (configurable) ● GPRS mobile station class B
DATA GPRS	<ul style="list-style-type: none"> ● GPRS data downlink transfer: max. 85.6kbps ● GPRS data uplink transfer: max. 85.6kbps ● Coding scheme: CS-1, CS-2, CS-3 and CS-4 ● Support the protocols PAP (Password Authentication Protocol) usually used for PPP connections ● Internet service protocols TCP/UDP, FTP, PPP, HTTP, NTP, PING ● Support Packet Broadcast Control Channel (PBCCH) ● Support Unstructured Supplementary Service Data (USSD)
Temperature Range	<ul style="list-style-type: none"> ● Normal operation: -35°C ~ +80°C ● Restricted operation: -40°C ~ -35°C and +80°C ~ +85°C ¹⁾ ● Storage temperature: -45°C ~ +90°C
Bluetooth	<ul style="list-style-type: none"> ● Support Bluetooth specification 3.0 ● Output Power: Class 1 (1W)
SMS	<ul style="list-style-type: none"> ● Text and PDU mode ● SMS storage: SIM card
SIM Interface	Support SIM card: 1.8V, 3.0V
Audio Features	Speech codec modes: <ul style="list-style-type: none"> ● Half Rate (ETS 06.20) ● Full Rate (ETS 06.10) ● Enhanced Full Rate (ETS 06.50/06.60/06.80) ● Adaptive Multi-Rate (AMR) ● Echo Suppression ● Noise Reduction
UART Interfaces	UART Port:

- Seven lines on UART port interface
- Used for AT command, GPRS data
- Multiplexing function
- Support autobauding from 4800bps to 115200bps

Debug Port:

- Two lines on debug port interface DBG_TXD and DBG_RXD
- Debug Port only used for firmware debugging

Auxiliary Port:

- Used for AT command

Phonebook Management Support phonebook types: SM, ME, ON, MC, RC, DC, LD, LA

SIM Application Toolkit Support SAT class 3, GSM 11.14 Release 99

Real Time Clock Supported

Physical Characteristics Size: 15.8±0.15 × 17.7±0.15 × 2.3±0.2mm
Weight: Approx. 1.3g

Firmware Upgrade Firmware upgrade via UART Port

Antenna Interface Connected to antenna pad with 50 Ohm impedance control

NOTE

¹⁾When the module works within this temperature range, the deviations from the GSM specification may occur. For example, the frequency error or the phase error will be increased.

Table 2: Coding Schemes and Maximum Net Data Rates over Air Interface

Coding Scheme	1 Timeslot	2 Timeslot	4 Timeslot
CS-1	9.05kbps	18.1kbps	36.2kbps
CS-2	13.4kbps	26.8kbps	53.6kbps
CS-3	15.6kbps	31.2kbps	62.4kbps
CS-4	21.4kbps	42.8kbps	85.6kbps

2.3. Functional Diagram

The following figure shows a block diagram of M66 and illustrates the major functional parts.

- Radio frequency part
- Power management
- The peripheral interface
 - Power supply
 - Turn-on/off interface
 - UART interface
 - Audio interface
 - PCM interface
 - SIM interface
 - ADC interface
 - RF interface
 - BT interface

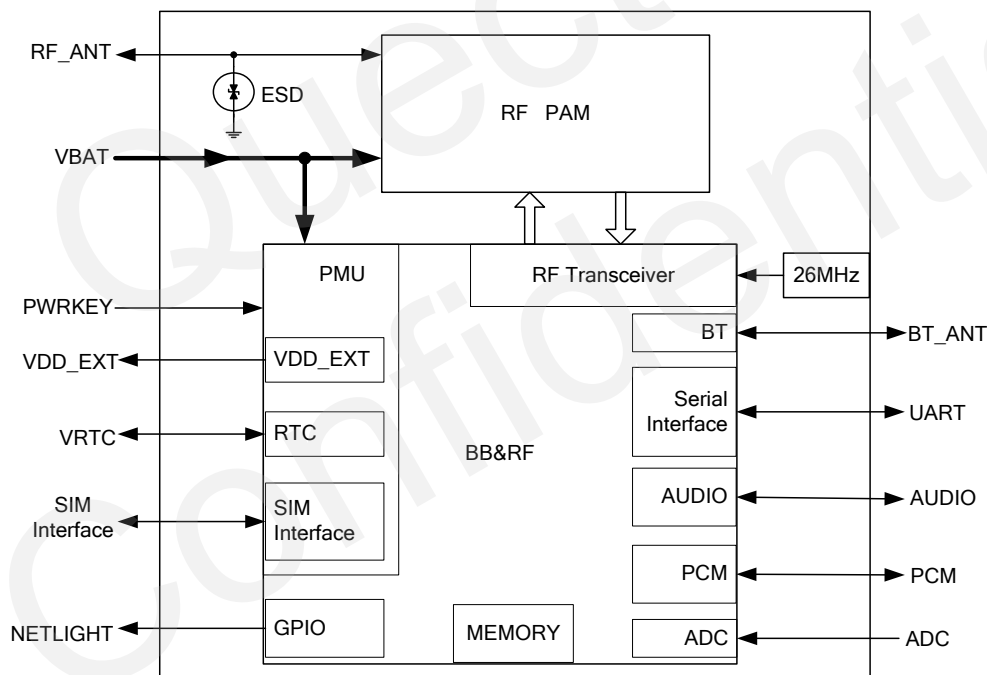


Figure 1: Module Functional Diagram

2.4. Evaluation Board

In order to help you to develop applications with M66, Quectel supplies an evaluation board (EVB), RS-232 to USB cable, power adapter, earphone, antenna and other peripherals to control or test the module. For details, please refer to the **document [12]**.

3 Application Interface

The module adopts LCC package and has 44 pins. The following chapters provide detailed descriptions about these pins.

- Power supply
- Power on/down
- Power Saving
- RTC
- Serial interfaces
- Audio interfaces
- PCM interface
- SIM Card interface
- ADC

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3.1. Pin of Module

3.1.1. Pin Assignment

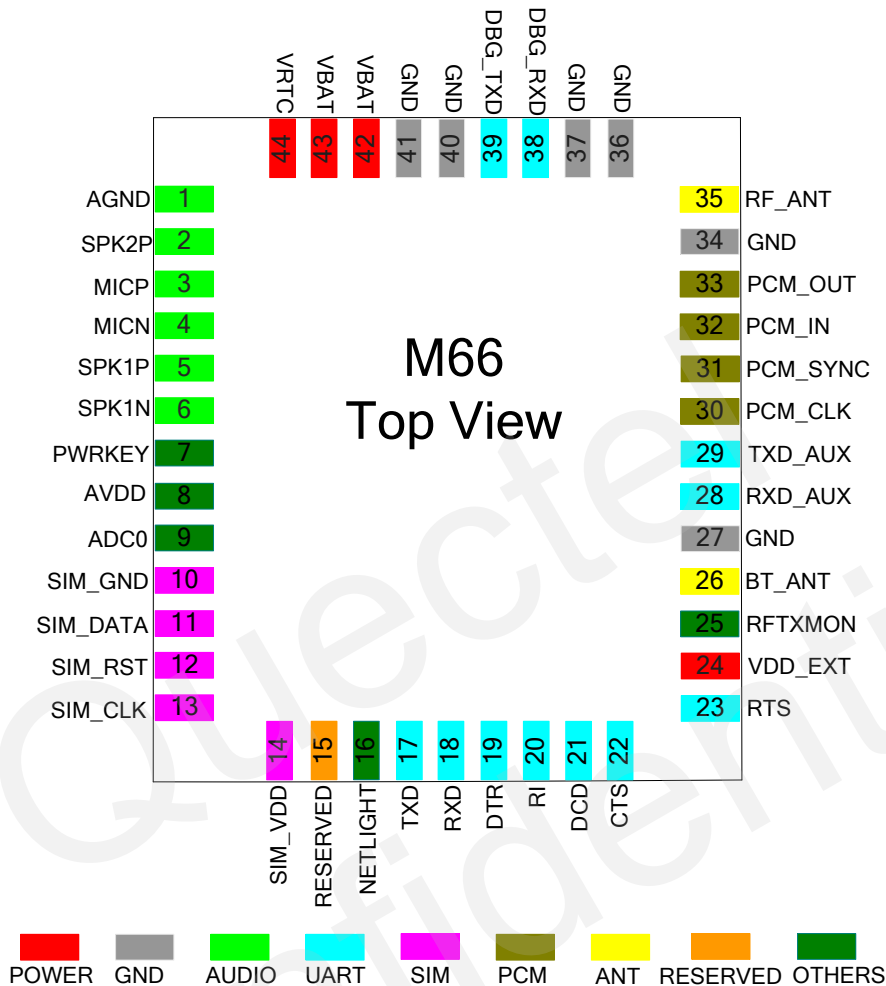


Figure 2: Pin Assignment

NOTE

Keep all reserved pins open.

3.1.2. Pin Description

Table 3: IO Parameters Definition

Type	Description
IO	Bidirectional input/output
DI	Digital input
DO	Digital output
PI	Power input
PO	Power output
AI	Analog input
AO	Analog output

Table 4: Pin Description

Power Supply					
PIN Name	PIN No.	I/O	Description	DC Characteristics	Comment
VBAT	42,43	PI	Main power supply of module: VBAT=3.3V~4.6V	$V_{I\max}=4.6V$ $V_{I\min}=3.3V$ $V_{I\text{norm}}=4.0V$	Make sure that supply sufficient current in a transmitting burst typically rises to 1.6A.
VRTC	44	IO	Power supply for RTC when VBAT is not supplied for the system. Charging for backup battery or golden capacitor when the VBAT is applied.	$V_{I\max}=3.3V$ $V_{I\min}=1.5V$ $V_{I\text{norm}}=2.8V$ $V_{O\max}=3V$ $V_{O\min}=2V$ $V_{O\text{norm}}=2.8V$ $I_{\text{out(max)}}=2\text{mA}$ $I_{\text{in}}\approx 10\mu\text{A}$	If unused, keep this pin open.
VDD_EXT	24	PO	Supply 2.8V voltage for external circuit.	$V_{O\max}=2.9V$ $V_{O\min}=2.7V$ $V_{O\text{norm}}=2.8V$ $I_{O\max}=20\text{mA}$	1. If unused, keep this pin open. 2. Recommend to add a 2.2~4.7uF bypass capacitor,

when using this pin for power supply.

	27,34		
GND	36,37		Ground
	40,41		

Turn On/off

PIN Name	PIN No.	I/O	Description	DC Characteristics	Comment
PWR KEY	7	DI	Power on/off key. PWRKEY should be pulled down for a moment to turn on or turn off the system.	$V_{ILmax}=0.1 \times V_{BAT}$ $V_{IHmin}=0.6 \times V_{BAT}$ $V_{IHmax}=3.1V$	

Audio Interface

PIN Name	PIN No.	I/O	Description	DC Characteristics	Comment
MICP MICN	3, 4	AI	Positive and negative voice input		If unused, keep these pins open.
SPK1P SPK1N	5, 6	AO	Channel 1 positive and negative voice output		If unused, keep these pins open.
SPK2P	2	AO	Channel 2 voice output	Refer to Section 3.8	Support both voice and ringtone output.
AGND	1		Analog ground. Separate ground connection for external audio circuits.		If unused, keep this pin open.

Network Status Indicator

PIN Name	PIN No.	I/O	Description	DC Characteristics	Comment
NETLIG HT	16	DO	Network status indication	$V_{OHmin}=0.85 \times V_{DD_EXT}$ $V_{OLmax}=0.15 \times V_{DD_EXT}$	If unused, keep this pin open.

UART Port

PIN Name	PIN No.	I/O	Description	DC Characteristics	Comment
TXD	17	DO	Transmit data	$V_{ILmin}=0V$	If only use TXD, RXD and GND to communicate,
RXD	18	DI	Receive data	$V_{ILmax}=0.25 \times V_{DD_EXT}$	

DTR	19	DI	Data terminal ready	$V_{IHmin} = 0.75 \times VDD_EXT$	recommended connecting RTS to GND via 0R resistor and keeping other pins open.
RI	20	DI	Ring indication	$V_{IHmax} = VDD_EXT + 0.3$	
DCD	21	DO	Data carrier detection	$V_{OHmin} = 0.85 \times VDD_EXT$	
CTS	22	DO	Clear to send	$V_{OLmax} = 0.15 \times VDD_EXT$	
RTS	23	DI	Request to send		

Debug Port

PIN Name	PIN No.	I/O	Description	DC Characteristics	Comment
DBG_TXD	39	DO	Transmit data	Same as above	If unused, keep these pins open.
DBG_RXD	38	DI	Receive data		

Auxiliary Port

PIN Name	PIN No.	I/O	Description	DC Characteristics	Comment
TXD_AUX	29	DO	Transmit data	Same as above	If unused, keep these pins open.
RXD_AUX	28	DI	Receive data		

SIM Interface

PIN Name	PIN No.	I/O	Description	DC Characteristics	Comment
SIM_VDD	14	PO	Power supply for SIM card	The voltage can be selected by software automatically. Either 1.8V or 3.0V.	All signals of SIM interface should be protected against ESD with a TVS diode array. Maximum trace length is 200mm from the module pad to SIM card holder.
SIM_CLK	13	DO	SIM clock	$V_{OLmax} = 0.15 \times SIM_VDD$ $V_{OHmin} = 0.85 \times SIM_VDD$	
SIM_DATA	11	IO	SIM data	$V_{ILmax} = 0.25 \times SIM_VDD$ $V_{IHmin} = 0.75 \times SIM_VDD$ $V_{OLmax} = 0.15 \times SIM_VDD$ $V_{OHmin} = 0.85 \times SIM_VDD$	

SIM_ RST	12	DO	SIM reset	$V_{OLmax} = 0.15 \times SIM_VDD$ $V_{OHmin} = 0.85 \times SIM_VDD$
----------	----	----	-----------	--

SIM_ GND	10		SIM ground	
----------	----	--	------------	--

ADC

PIN Name	PIN No.	I/O	Description	DC Characteristics	Comment
AVDD	8	PO	Reference voltage of ADC circuit	$V_{Omax} = 2.9V$ $V_{Omin} = 2.7V$ $V_{Onorm} = 2.8V$	If unused, keep this pin open.
ADC0	9	AI	General purpose analog to digital converter.	Voltage range: 0V to 2.8V	If unused, keep this pin open.

PCM

PIN Name	PIN No.	I/O	Description	DC Characteristics	Comment
PCM_ CLK	30	DO	PCM clock	$V_{ILmin} = 0V$ $V_{ILmax} = 0.25 \times VDD_EXT$	
PCM_ SYNC	31	DO	PCM frame synchronization	$V_{IHmin} = 0.75 \times VDD_EXT$ $V_{IHmax} = VDD_EXT + 0.3$	
PCM_ IN	32	DI	PCM data input	$V_{OHmin} = 0.85 \times VDD_EXT$	
PCM_ OUT	33	DO	PCM data output	$V_{OLmax} = 0.15 \times VDD_EXT$	

Antenna Interface

PIN Name	PIN No.	I/O	Description	DC Characteristics	Comment
RF_ ANT	35	IO	GSM antenna pad	Impedance of 50Ω	
BT_ ANT	26	IO	BT antenna pad	Impedance of 50Ω	

Transmitting Signal Indication

PIN Name	PIN No.	I/O	Description	DC Characteristics
RFTX MON	25	DO	Transmission signal indication	$V_{OHmin} = 0.85 \times VDD_EXT$

$$V_{OLmax} = 0.15 \times VDD_EXT$$

Other Interface

PIN Name	PIN No.	I/O	Description	DC Characteristics	Comment
RESER VED	15				Keep these pins open.

3.2. Operating Modes

The table below briefly summarizes the various operating modes in the following chapters.

Table 5: Overview of Operating Modes

Mode	Function
Normal Operation	GSM/GPRS Sleep After enabling sleep mode by AT+QSCLK=1 , the module will automatically enter into Sleep Mode if DTR is set to high level and there is no interrupt (such as GPIO interrupt or data on UART port). In this case, the current consumption of module will reduce to the minimal level. During Sleep Mode, the module can still receive paging message and SMS from the system normally.
	GSM IDLE Software is active. The module has registered to the GSM network, and the module is ready to send and receive GSM data.
	GSM TALK GSM connection is ongoing. In this mode, the power consumption is decided by the configuration of Power Control Level (PCL), dynamic DTX control and the working RF band.
	GPRS IDLE The module is not registered to GPRS network. The module is not reachable through GPRS channel.
	GPRS STANDBY The module is registered to GPRS network, but no GPRS PDP context is active. The SGSN knows the Routing Area where the module is located at.
	GPRS READY The PDP context is active, but no data transfer is ongoing. The module is ready to receive or send GPRS data. The SGSN knows the cell where the module is located at.
	GPRS DATA There is GPRS data in transfer. In this mode, power consumption is decided by the PCL, working RF band and GPRS multi-slot configuration.

POWER DOWN	Normal shutdown by sending the AT+QPOWD=1 command or using the PWRKEY pin. The power management ASIC disconnects the power supply from the base band part of the module, and only the power supply for the RTC is remained. Software is not active. The UART interfaces are not accessible. Operating voltage (connected to VBAT) remains applied.
Minimum Functionality Mode (without removing power supply)	AT+CFUN command can set the module to a minimum functionality mode without removing the power supply. In this case, the RF part of the module will not work or the SIM card will not be accessible, or both RF part and SIM card will be disabled, but the UART port is still accessible. The power consumption in this case is very low.

3.3. Power Supply

3.3.1. Power Features of Module

The power supply is one of the key issues in designing GSM terminals. Because of the 577us radio burst in GSM every 4.615ms, power supply must be able to deliver high current peaks in a burst period. During these peaks, drops on the supply voltage must not exceed minimum working voltage of module.

For the M66 module, the max current consumption could reach to 1.6A during a burst transmission. It will cause a large voltage drop on the VBAT. In order to ensure stable operation of the module, it is recommended that the max voltage drop during the burst transmission does not exceed 400mV.

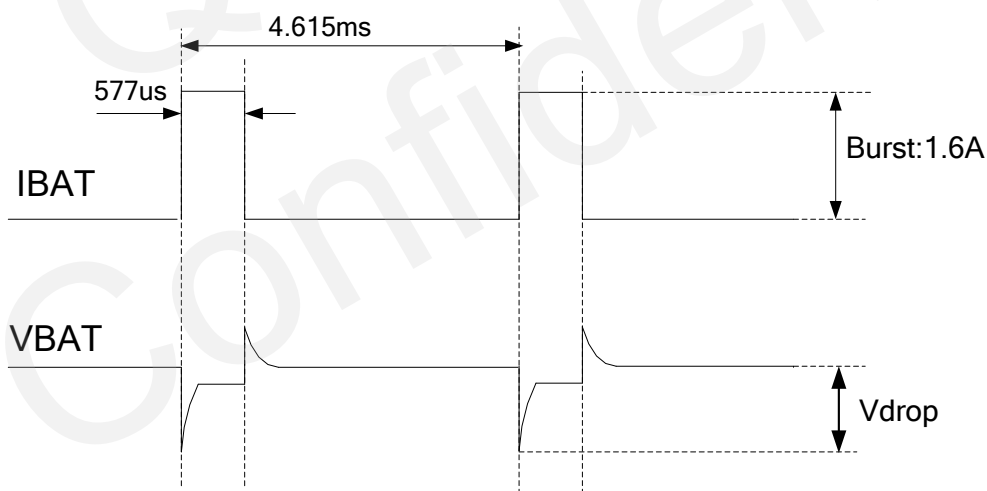


Figure 3: Voltage Ripple during Transmitting

3.3.2. Decrease Supply Voltage Drop

The power supply range of the module is 3.3V to 4.6V. Make sure that the input voltage will never drop below 3.3V even in a burst transmission. If the power voltage drops below 3.3V, the module could turn off

automatically. For better power performance, it is recommended to place a 100uF tantalum capacitor with low ESR (ESR=0.7Ω) and ceramic capacitor 100nF, 33pF and 10pF near the VBAT pin. The reference circuit is illustrated in Figure 4.

The VBAT route should be wide enough to ensure that there is not too much voltage drop during burst transmission. The width of trace should be no less than 2mm and the principle of the VBAT route is the longer route, the wider trace.

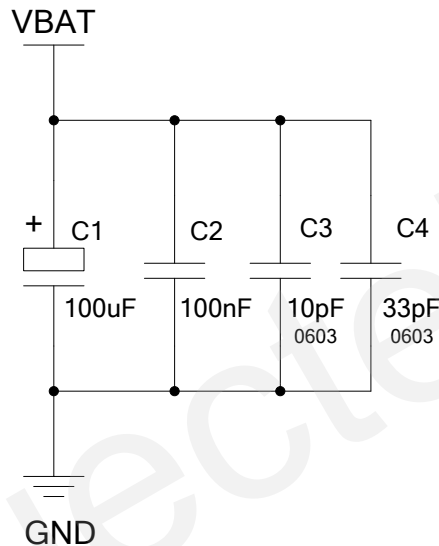


Figure 4: Reference Circuit for the VBAT Input

3.3.3. Reference Design For Power Supply

The power design for the module is very important, since the performance of power supply for the module largely depends on the power source. The power supply is capable of providing the sufficient current up to 2A at least. If the voltage drop between the input and output is not too high, it is suggested to use a LDO as module's power supply. If there is a big voltage difference between the input source and the desired output (VBAT), a switcher power converter is recommended to be used as a power supply.

Figure 5 shows a reference design for +5V input power source. The designed output for the power supply is 4.16V and the maximum load current is 3A. In addition, in order to get a stable output voltage, a zener diode is placed close to the pins of VBAT. As to the zener diode, it is suggested to use a zener diode whose reverse zener voltage is 5.1V and dissipation power is more than 1 Watt.

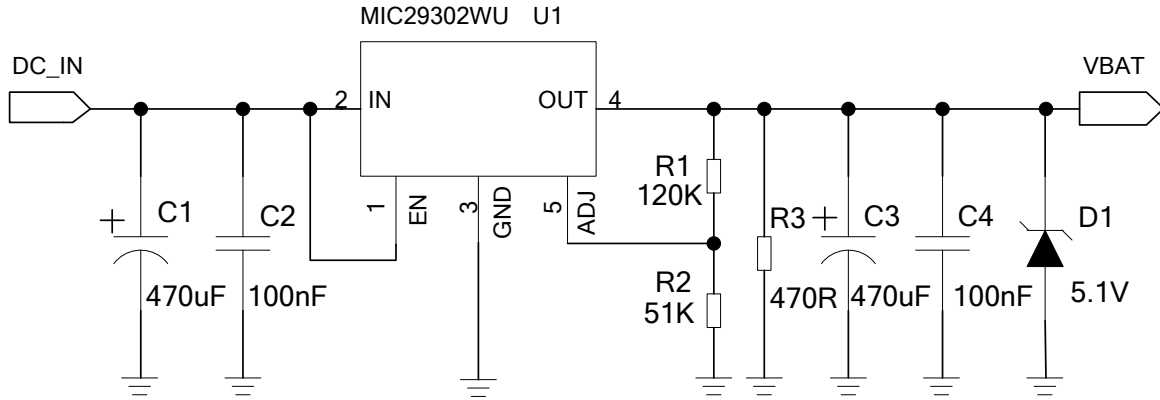


Figure 5: Reference Circuit for Power Supply

3.3.4. Monitor Power Supply

To monitor the supply voltage, customer can use the **AT+CBC** command which includes three parameters: charging status, remaining battery capacity and voltage value (in mV). It returns the 0-100 percent of battery capacity and actual value measured between VBAT and GND. The voltage is automatically measured in period of 5s. The displayed voltage (in mV) is averaged over the last measuring period before the **AT+CBC** command is executed.

For details, please refer to the *document [1]*.

3.4. Power On and Down Scenarios

3.4.1. Power On

The module can be turned on by driving the pin PWRKEY to a low level voltage. An open collector driver circuit is suggested to control the PWRKEY. A simple reference circuit is illustrated as below.

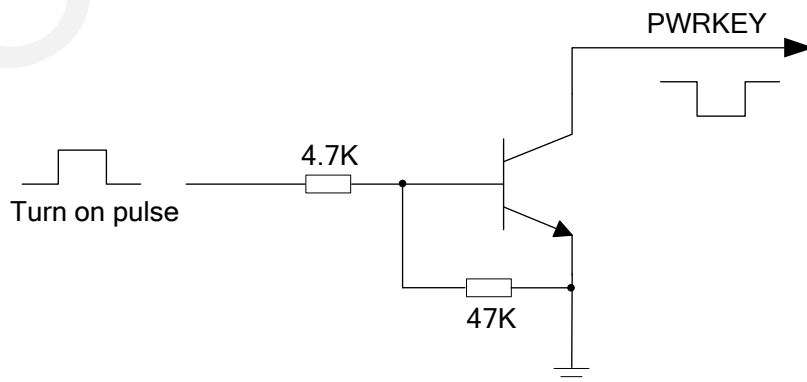


Figure 6: Turn on the Module with an Open-collector Driver

NOTE

M66 module is set to autobauding mode (**AT+IPR=0**) by default. In the autobauding mode, URC **RDY** is not reported to the host controller after module is powered on. When the module is powered on after a delay of 2 or 3 seconds, it can receive AT command. Host controller should first send an **AT** or **at** string in order that the module can detect baud rate of host controller, and it should send the second or the third **AT** or **at** string until receiving **OK** string from the module. Then enter **AT+IPR=x;&W** to set a fixed baud rate for the module and save the configuration to flash memory of the module. After these configurations, the URC **RDY** would be received from the UART port of the module every time when the module is powered on. For more details, refer to the section **AT+IPR** in *document [1]*.

The other way to control the PWRKEY is through a button directly. A TVS component is indispensable to be placed nearby the button for ESD protection. For the best performance, the TVS component must be placed nearby the button. When pressing the key, electrostatic strike may generate from finger. A reference circuit is shown in the following figure.

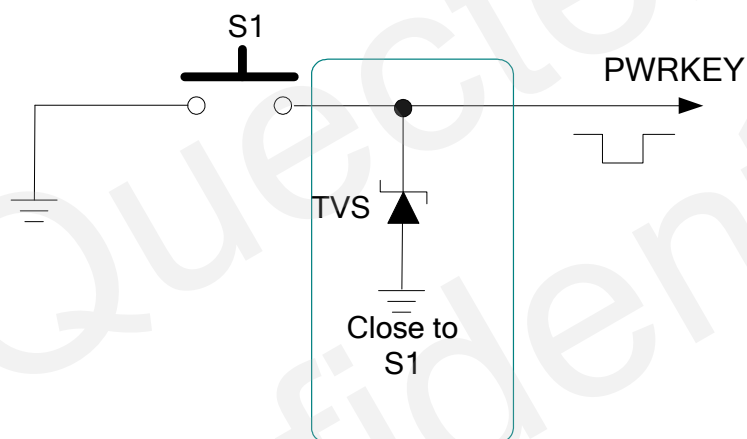


Figure 7: Turn on the Module with a Button

The turn-on timing is illustrated as the following figure.

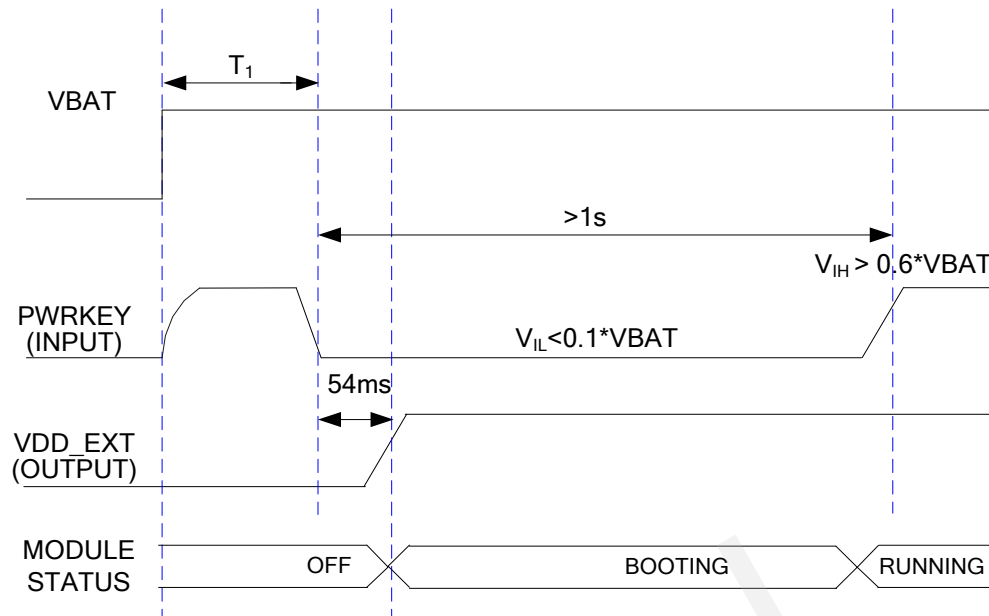


Figure 8: Turn-on Timing

NOTE

Make sure that VBAT is stable before pulling down PWRKEY pin. The time of T_1 is recommended to be 100ms.

3.4.2. Power Down

The following procedures can be used to turn off the module:

- Normal power down procedure: Turn off module using the PWRKEY pin
- Normal power down procedure: Turn off module using command **AT+QPOWD**
- Over-voltage or under-voltage automatic shutdown: Take effect when over-voltage or under-voltage is detected

3.4.2.1. Power Down Module Using the PWRKEY Pin

It is a safe way to turn off the module by driving the PWRKEY to a low level voltage for a certain time. The power down scenario is illustrated in Figure 9.

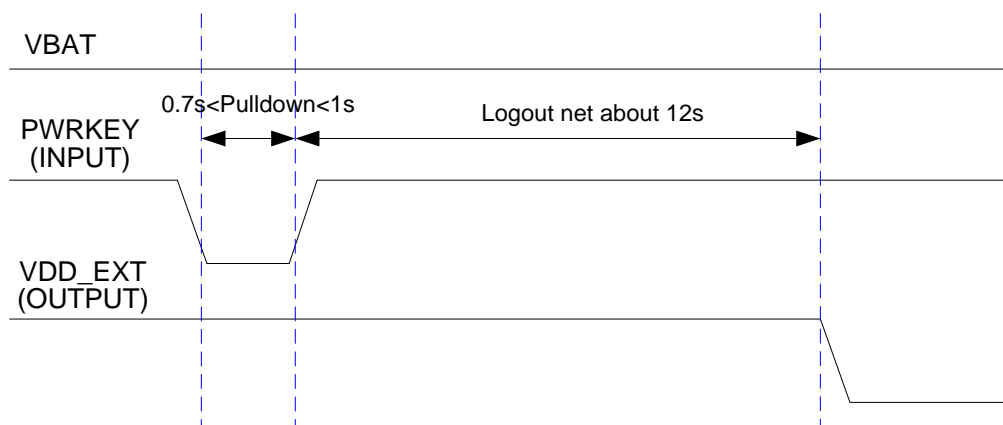


Figure 9: Turn-off Timing

The power down procedure causes the module to log off from the network and allows the firmware to save important data before completely disconnecting the power supply.

Before the completion of the power down procedure, the module sends out the result code shown below:

NORMAL POWER DOWN

NOTE

This result code does not appear when autobauding is active and DTE and DCE are not correctly synchronized after start-up. The module is recommended to set a fixed baud rate.

After that moment, no further AT commands can be executed. Then the module enters the power down mode, the RTC is still active.

3.4.2.2. Power Down Module Using AT Command

It is also a safe way to turn off the module via AT command **AT+QPOWD=1**. This command will let the module log off from the network and allow the firmware to save important data before completely disconnecting the power supply.

Before the completion of the power down procedure the module sends out the result code shown below:

NORMAL POWER DOWN

After that moment, no further AT commands can be executed. And then the module enters the power down mode, only the RTC is still active.

Please refer to the **document [1]** for details about the AT command **AT+QPOWD**.

3.4.2.3. Over-voltage or Under-voltage Automatic Shutdown

The module will constantly monitor the voltage applied on the VBAT, if the voltage is $\leq 3.5V$, the following URC will be presented:

UNDER_VOLTAGE WARNING

If the voltage is $\geq 4.5V$, the following URC will be presented:

OVER_VOLTAGE WARNING

The normal input voltage range is from 3.3V to 4.6V. If the voltage is $>4.6V$ or $<3.3V$, the module would automatically shut down itself.

If the voltage is $<3.3V$, the following URC will be presented:

UNDER_VOLTAGE POWER DOWN

If the voltage is $>4.6V$, the following URC will be presented:

OVER_VOLTAGE POWER DOWN

NOTE

These Unsolicited result codes do not appear when autobauding is active and DTE and DCE are not correctly synchronized after start-up. The module is recommended to set to a fixed baud rate.

After that moment, no further AT commands can be executed. The module logs off from network and enters power down mode, and RTC is still active.

3.4.3. Restart

You can restart the module by driving the PWRKEY to a low level voltage for a certain time, which is similar to the way of turning on module. Before restarting the module, at least 500ms should be delayed after detecting the low level of VDD_EXT. The restart timing is illustrated as the following figure.

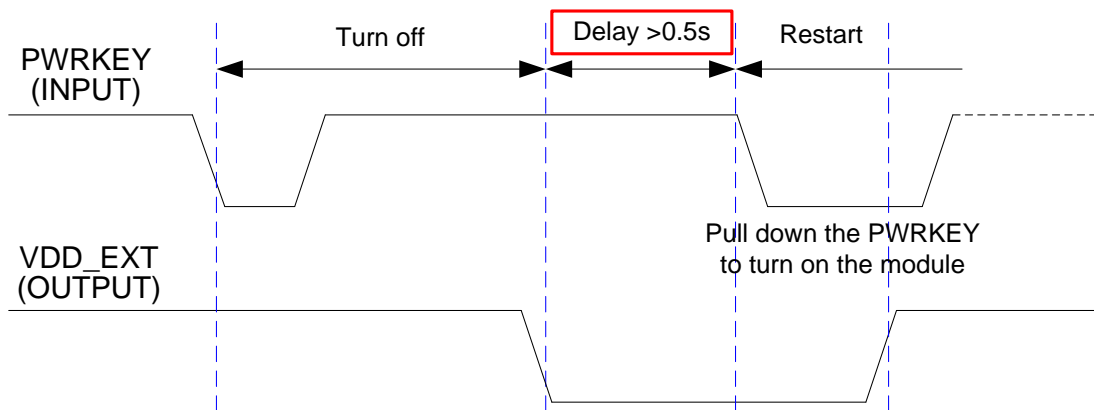


Figure 10: Timing of Restarting System

3.5. Power Saving

Based on system requirements, there are several actions to drive the module to enter low current consumption status. For example, **AT+CFUN** can be used to set module into minimum functionality mode and DTR hardware interface signal can be used to lead system to SLEEP mode.

3.5.1. Minimum Functionality Mode

Minimum functionality mode reduces the functionality of the module to a minimum level. The consumption of the current can be minimized when the slow clocking mode is activated at the same time. The mode is set with the **AT+CFUN** command which provides the choice of the functionality levels <fun>=0, 1, 4.

- 0: minimum functionality
- 1: full functionality (default)
- 4: disable both transmitting and receiving of RF part

If the module is set to minimum functionality by **AT+CFUN=0**, the RF function and SIM card function would be disabled. In this case, the UART port is still accessible, but all AT commands related with RF function or SIM card function will be not available.

If the module has been set by the command with **AT+CFUN=4**, the RF function will be disabled, but the UART port is still active. In this case, all AT commands related with RF function will be not available.

After the module is set by **AT+CFUN=0** or **AT+CFUN=4**, it can return to full functionality by **AT+CFUN=1**.

For detailed information about **AT+CFUN**, please refer to the *document [1]*.

3.5.2. SLEEP Mode

The SLEEP mode is disabled by default. You can enable it by **AT+QSCLK=1**. On the other hand, the default setting is **AT+QSCLK=0** and in this mode, the module cannot enter SLEEP mode.

When the module is set by the command with **AT+QSCLK=1**, you can control the module to enter or exit from the SLEEP mode through pin DTR. When DTR is set to high level, and there is no on-air or hardware interrupt such as GPIO interrupt or data on UART port, the module will enter SLEEP mode automatically. In this mode, the module can still receive voice, SMS or GPRS paging from network, but the UART port does not work.

3.5.3. Wake Up Module From SLEEP Mode

When the module is in the SLEEP mode, the following methods can wake up the module.

- If the DTR Pin is set low, it would wake up the module from the SLEEP mode. The UART port will be active within 20ms after DTR is changed to low level.
- Receive a voice or data call from network wakes up module.
- Receive an SMS from network wakes up module.

NOTE

DTR pin should be held at low level during communication between the module and DTE.

3.5.4. Summary of State Transition

Table 6: Summary of State Transition

Current Mode	Next Mode		
	Power Down	Normal Mode	Sleep Mode
Power Down		Use PWRKEY	
Normal Mode	AT+QPOWD, use PWRKEY pin		Use AT command AT+QSCLK=1 and pull up DTR
SLEEP Mode	Use PWRKEY pin	Pull DTR down or incoming call or SMS or GPRS	

3.6. RTC Backup

The RTC (Real Time Clock) function is supported by M66 module. The RTC is designed to work with an internal power supply. If VBAT voltage is not present, a backup power supply such as a coin-cell battery (rechargeable or non-chargeable) or a super-cap can be used. The VRTC pin is voltage input for RTC and a 1.5K resistor is integrated in the module for peak current limit.

The following figures show various sample circuits for RTC backup.

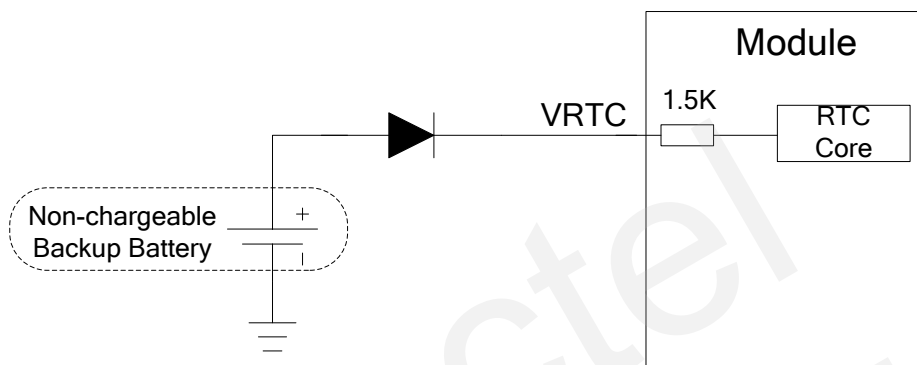


Figure 11: RTC Supply from a Non-chargeable Battery

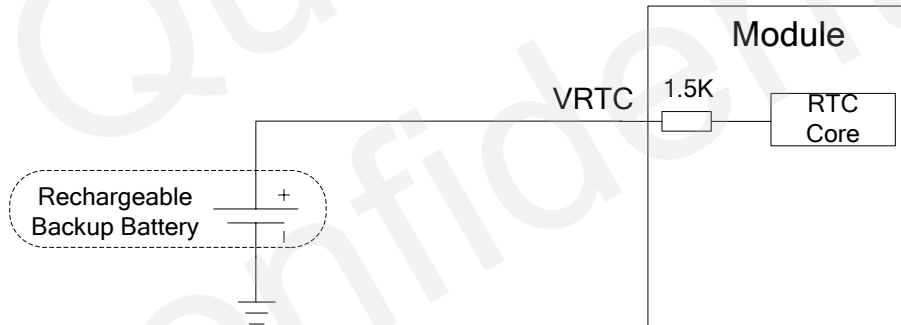


Figure 12: RTC Supply from a Rechargeable Battery

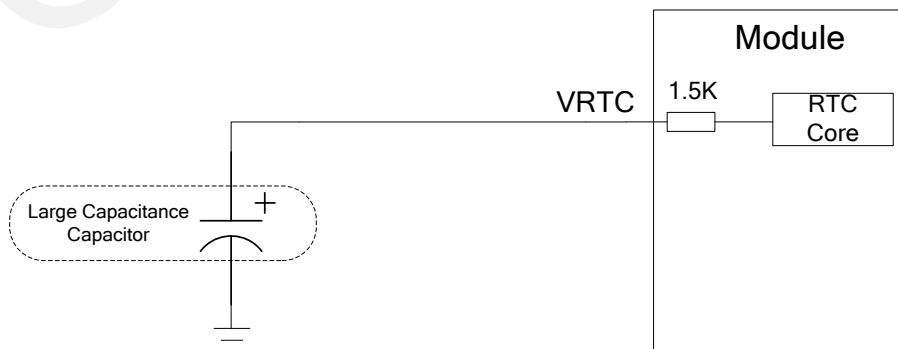


Figure 13: RTC Supply from a Capacitor

The following figure shows the charging characteristics of a coin-type rechargeable battery XH414H-IV01E from Seiko.

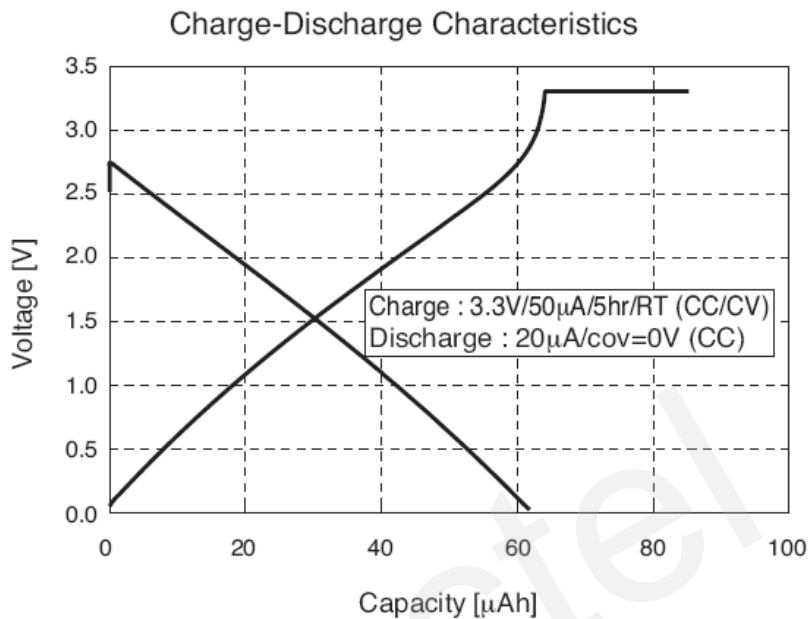


Figure 14: Charging Characteristics of Seiko's XH414H-IV01E

3.7. Serial Interfaces

The module provides three serial ports: UART Port, Debug Port and Auxiliary UART Port. The module is designed as a DCE (Data Communication Equipment), following the traditional DCE-DTE (Data Terminal Equipment) connection. Autobauding function supports baud rate from 4800bps to 115200bps.

The UART Port:

- TXD: Send data to RXD of DTE.
- RXD: Receive data from TXD of DTE.
- RTS: Request to send.
- CTS: Clear to send.
- DTR: DTE is ready and inform DCE (this pin can wake the module up).
- RI: Ring indicator (when the call, SMS, data of the module are coming, the module will output signal to inform DTE).
- DCD: Data carrier detection (the validity of this pin demonstrates the communication link is set up).

NOTE

The module disables hardware flow control by default. When hardware flow control is required, RTS and CTS should be connected to the host. AT command **AT+IFC=2,2** is used to enable hardware flow control. AT command **AT+IFC=0,0** is used to disable the hardware flow control. For more details, please refer to the **document [1]**.

The Debug Port:

- DBG_TXD: Send data to the COM port of computer.
- DBG_RXD: Receive data from the COM port of computer.

The Auxiliary UART Port:

- TXD_AUX: Send data to the RXD of DTE.
- RXD_AUX: Receive data from the TXD of DTE.

The logic levels are described in the following table.

Table 7: Logic Levels of the UART Interface

Parameter	Min.	Max.	Unit
V _{IL}	0	0.25×VDD_EXT	V
V _{IH}	0.75×VDD_EXT	VDD_EXT +0.3	V
V _{OL}	0	0.15×VDD_EXT	V
V _{OH}	0.85×VDD_EXT	VDD_EXT	V

Table 8: Pin Definition of the UART Interfaces

Interface	Pin No.	Pin Name	Description
UART Port	17	TXD	Transmit data
	18	RXD	Receive data
	19	DTR	Data terminal ready
	20	RI	Ring indication

	21	DCD	Data carrier detection
	22	CTS	Clear to send
	23	RTS	Request to send
Debug Port	38	DBG_RXD	Receive data
	39	DBG_TXD	Transmit data
Auxiliary UART Port	28	RXD_AUX	Receive data
	29	TXD_AUX	Transmit data

3.7.1. UART Port

3.7.1.1. The Feature of UART Port

- Seven lines on UART interface
- Contain data lines TXD and RXD, hardware flow control lines RTS and CTS, other control lines DTR, DCD and RI.
- Used for AT command, GPRS data, etc. Multiplexing function is supported on the UART Port. So far only the basic mode of multiplexing is available.
- Support the communication baud rates as the following:
300, 600, 1200, 2400, 4800, 9600, 14400, 19200, 28800, 38400, 57600, 115200.
- The default setting is autobauding mode. Support the following baud rates for Autobauding function:
4800, 9600, 19200, 38400, 57600, 115200.
- The module disables hardware flow control by default. AT command **AT+IFC=2,2** is used to enable hardware flow control.

After setting a fixed baud rate or autobauding, please send “AT” string at that rate. The UART port is ready when it responds “OK”.

Autobauding allows the module to detect the baud rate by receiving the string “AT” or “at” from the host or PC automatically, which gives module flexibility without considering which baud rate is used by the host controller. Autobauding is enabled by default. To take advantage of the autobauding mode, special attention should be paid according to the following requirements:

Synchronization between DTE and DCE:

When DCE (the module) powers on with the autobauding enabled, it is recommended to wait 2 to 3 seconds before sending the first AT character. After receiving the “OK” response, DTE and DCE are correctly synchronized.

If the host controller needs URC in the mode of autobauding, it must be synchronized firstly. Otherwise the URC will be discarded.

Restrictions on autobauding operation:

- The UART port has to be operated at 8 data bits, no parity and 1 stop bit (factory setting).
- The “At” and “aT” commands cannot be used.
- Only the strings “AT” or “at” can be detected (neither “At” nor “aT”).
- The Unsolicited Result Codes like **RDY**, **+CFUN: 1** and **+CPIN: READY** will not be indicated when the module is turned on with autobauding enabled and not be synchronized.
- Any other Unsolicited Result Codes will be sent at the previous baud rate before the module detects the new baud rate by receiving the first “AT” or “at” string. The DTE may receive unknown characters after switching to new baud rate.
- It is not recommended to switch to autobauding from a fixed baud rate.
- If autobauding is active it is not recommended to switch to multiplex mode.

NOTE

To assure reliable communication and avoid any problems caused by undetermined baud rate between DCE and DTE, it is strongly recommended to configure a fixed baud rate and save it instead of using autobauding after start-up. For more details, please refer to the Section **AT+IPR** in *document [1]*.

3.7.1.2. The Connection of UART

The connection between module and host using UART Port is very flexible. Three connection styles are illustrated as below.

Reference design for Full-Function UART connection is shown as below when it is applied in modulation-demodulation.

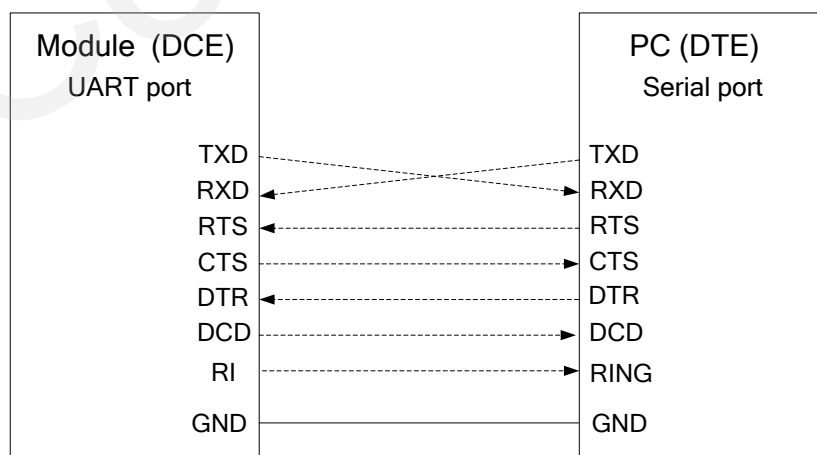


Figure 15: Reference Design for Full-Function UART

Three-line connection is shown as below.

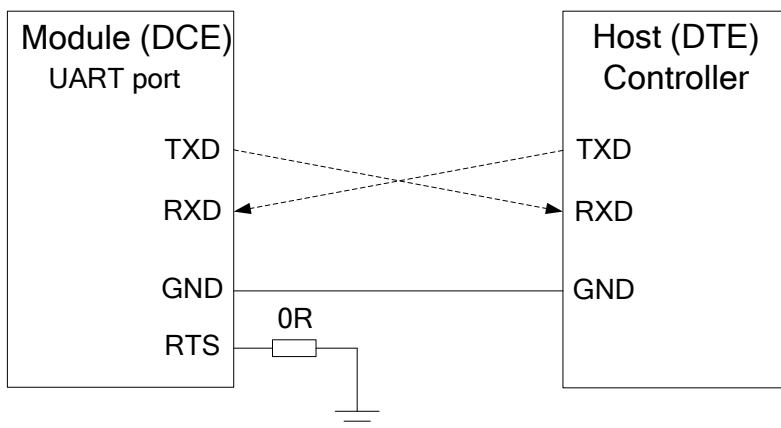


Figure 16: Reference Design for UART Port

UART Port with hardware flow control is shown as below. This connection will enhance the reliability of the mass data communication.

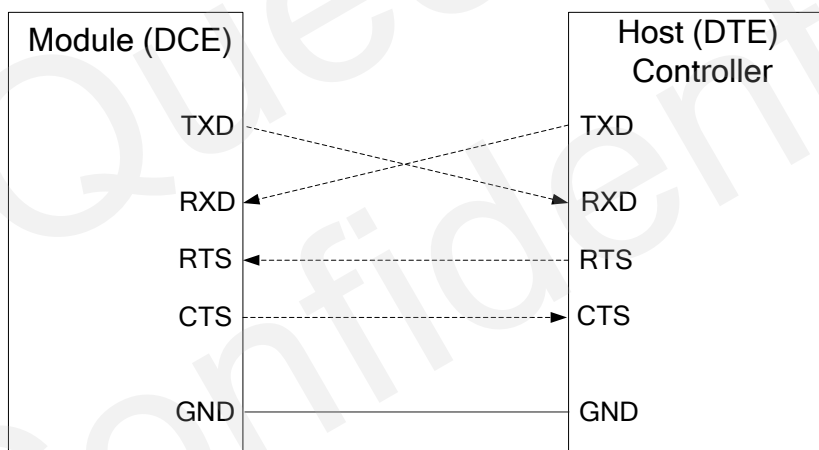


Figure 17: Reference Design for UART Port with Hardware Flow Control

3.7.1.3. Firmware Upgrade

The TXD, RXD can be used to upgrade firmware. The PWRKEY pin must be pulled down before firmware upgrade. The reference circuit is shown as below:

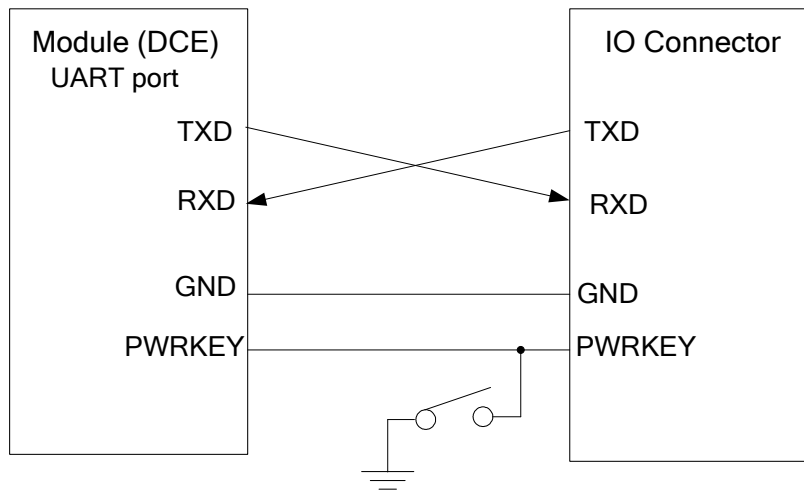


Figure 18: Reference Design for Firmware Upgrade

NOTE

The firmware of module might need to be upgraded due to certain reasons. It is recommended to reserve these pins in the host board for firmware upgrade. For detailed design, please refer to the **document [11]**.

3.7.2. Debug Port

- Two lines: DBG_TXD and DBG_RXD.
- It outputs log information automatically.
- Debug Port is only used for firmware debugging and its baud rate must be configured as 460800bps.

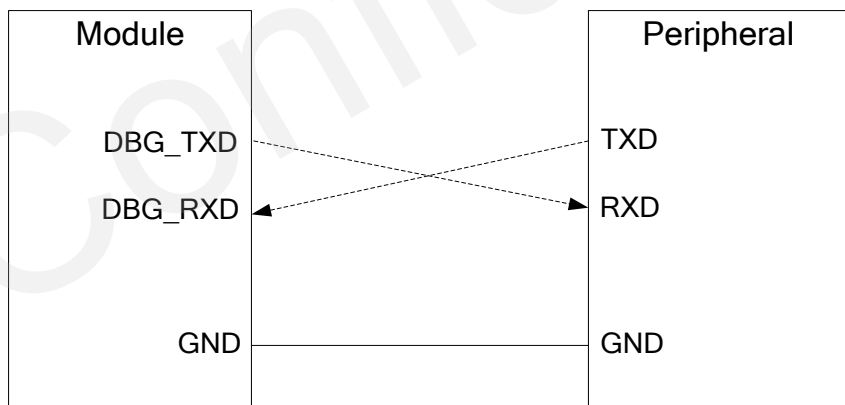


Figure 19: Reference Design for Debug Port

3.7.3. Auxiliary UART Port

- Two data lines: TXD_AUX and RXD_AUX.
- Auxiliary UART port is used for AT command only and does not support GPRS data, Multiplexing function etc.
- Auxiliary UART port supports the communication baud rates as the following:
1200, 2400, 4800, 9600, 14400, 19200, 28800, 38400, 57600, 115200.
- Auxiliary UART port could be used when you send **AT+QEAUART=1** string on the UART port.
- The default baud rate setting is 115200bps, and does not support autobauding. The baud rate can be modified by **AT+QSEDCB** command. For more details, please refer to the **document [1]**.

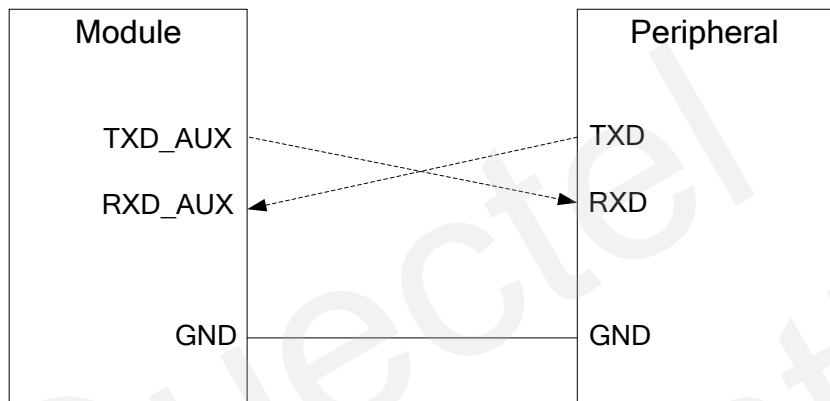


Figure 20: Reference Design for Auxiliary UART Port

3.7.4. UART Application

The reference design of 3.3V level match is shown as below. If the host is a 3V system, please change the 5.6K resistor to 10K.

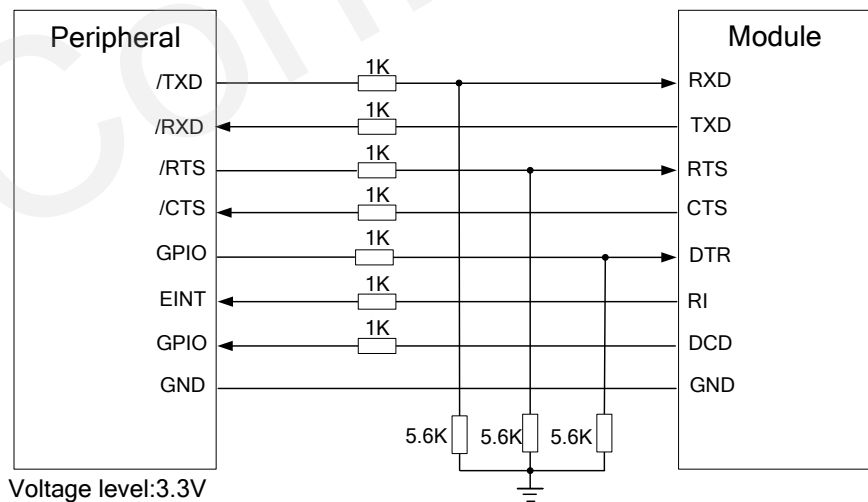


Figure 21: Level Match Design for 3.3V System

The following circuit shows a reference design for the communication between module and PC. Since the electrical level of module is 2.8V, so a RS-232 level shifter must be used.

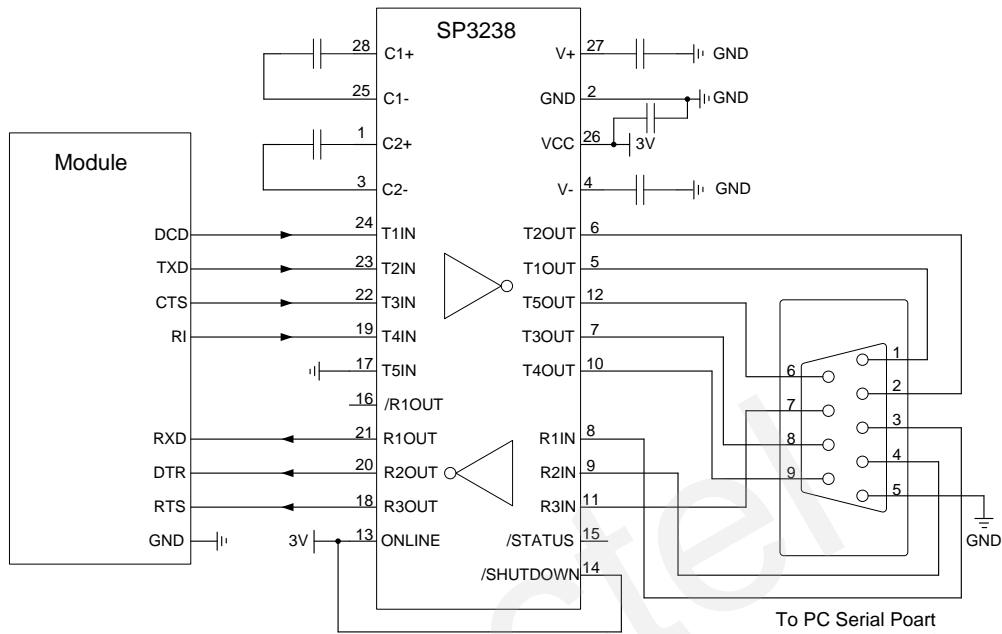


Figure 22: Level Match Design for RS-232

3.8. Audio Interfaces

The module provides one analogy input channels and two analogy output channels.

Table 9: Pin Definition of Audio Interface

Interface	Name	Pin NO.	Description
AIN/AOUT1	MICP	3	Microphone positive input
	MICN	4	Microphone negative input
	SPK1P	5	Channel 1 Audio positive output
	SPK1N	6	Channel 1 Audio negative output
AIN/AOUT2	MICP	3	Microphone positive input
	MICN	4	Microphone negative input
	SPK2P	2	Channel 2 Audio positive output
	AGND	1	Form a pseudo-differential pair with SPK2P

AIN can be used for input of microphone and line. An electret microphone is usually used. AIN are differential input channels.

AOUT1 is used for output of the receiver. This channel is typically used for a receiver built into a handset. AOUT1 channel is a differential channel.

AOUT2 is typically used with earphone. It is a single-ended and mono channel. SPK2P and AGND can establish a pseudo differential mode.

All of these three audio channels support voice and ringtone output, and so on, and can be switched by **AT+QAUDCH** command. For more details, please refer to the **document [1]**.

Use AT command **AT+QAUDCH** to select audio channel:

- 0--AIN/AOUT1, the default value is 0.
- 1--AIN/AOUT2, this channel is always used for earphone.

For each channel, you can use **AT+QMIC** to adjust the input gain level of microphone. You can also use **AT+CLVL** to adjust the output gain level of receiver and speaker. **AT+QSIDET** is used to set the side-tone gain level. For more details, please refer to the **document [1]**.

3.8.1. Decrease TDD Noise and other Noise

The 33pF capacitor is applied for filtering out 900MHz RF interference when the module is transmitting at GSM900MHz. Without placing this capacitor, TDD noise could be heard. Moreover, the 10pF capacitor here is for filtering out 1800MHz RF interference. However, the resonant frequency point of a capacitor largely depends on the material and production technique. Therefore, customer would have to discuss with its capacitor vendor to choose the most suitable capacitor for filtering out GSM850MHz, GSM900MHz, DCS1800MHz and PCS1900MHz separately.

The severity degree of the RF interference in the voice channel during GSM transmitting period largely depends on the application design. In some cases, GSM900 TDD noise is more severe; while in other cases, DCS1800 TDD noise is more obvious. Therefore, you can have a choice based on test results. Sometimes, even no RF filtering capacitor is required.

The capacitor which is used for filtering out RF noise should be close to audio interface or other audio interfaces. Audio alignment should be as short as possible.

In order to decrease radio or other signal interference, the position of RF antenna should be kept away from audio interface and audio alignment. Power alignment and audio alignment should not be parallel, and power alignment should be far away from audio alignment.

The differential audio traces have to be placed according to the differential signal layout rule.

3.8.2. Microphone Interfaces Design

AIN channel come with internal bias supply for external electret microphone. A reference circuit is shown in the following figure.

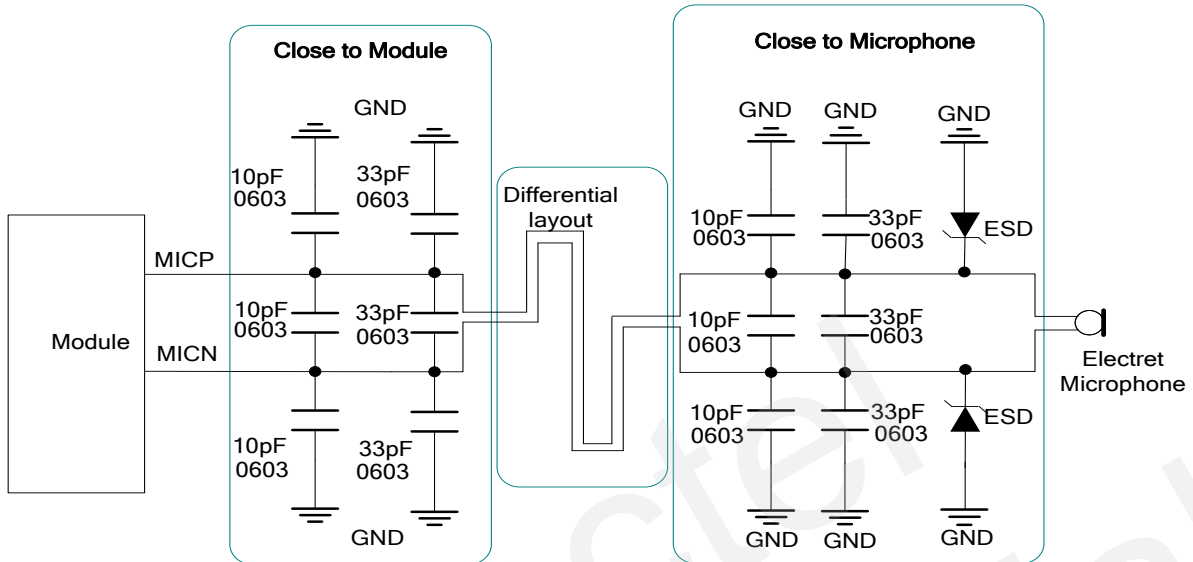


Figure 23: Reference Design for AIN

3.8.3. Receiver and Speaker Interface Design

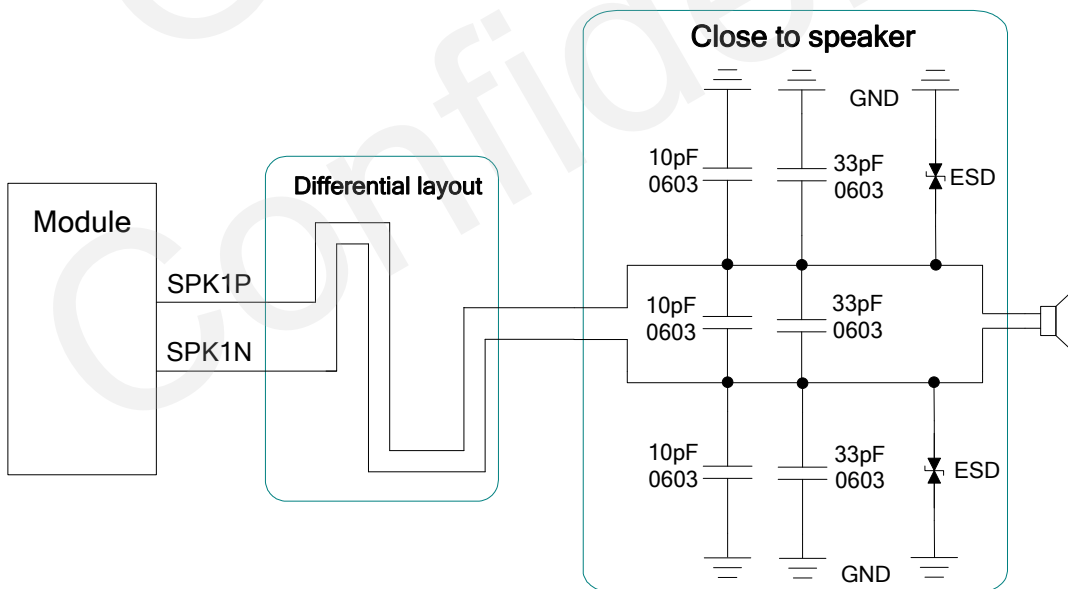


Figure 24: Reference Design for AOUT1

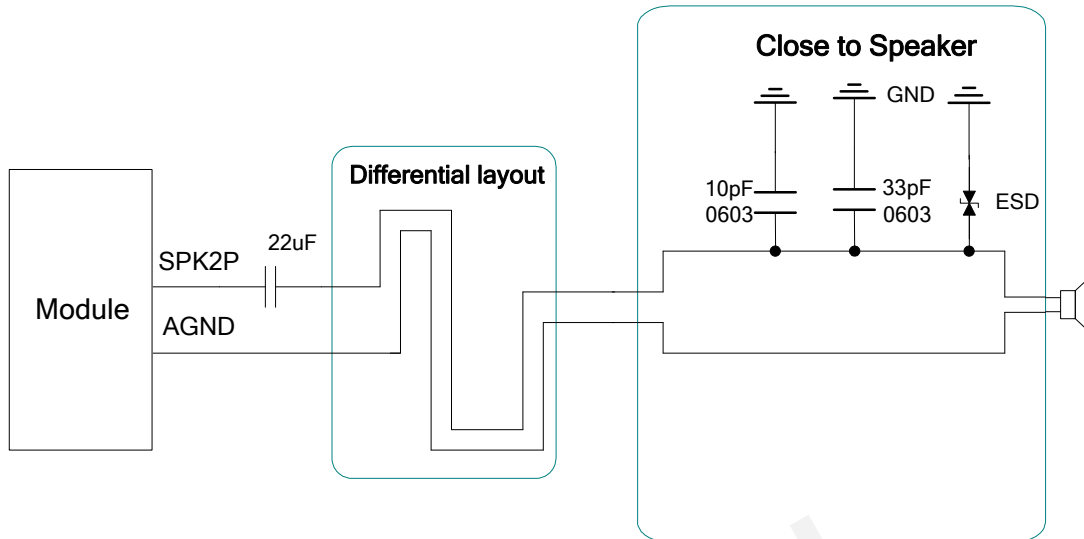


Figure 25: Handset Interface Design for AOUT2

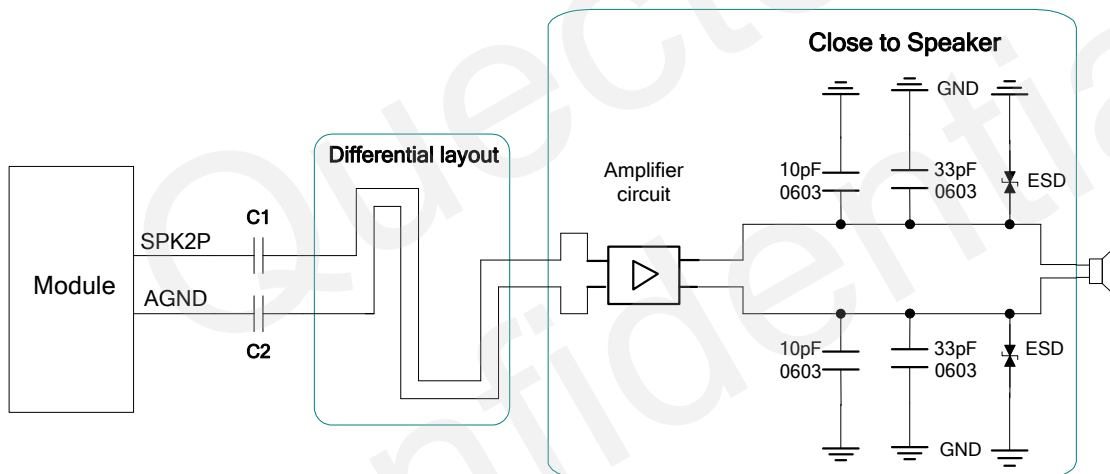


Figure 26: Speaker Interface Design with an Amplifier for AOUT2

Texas Instrument's TPA6205A1 is recommended for a suitable differential audio amplifier. There are plenty of excellent audio amplifiers in the market.

NOTE

The value of C1 and C2 here depends on the input impedance of audio amplifier.

3.8.4. Earphone Interface Design

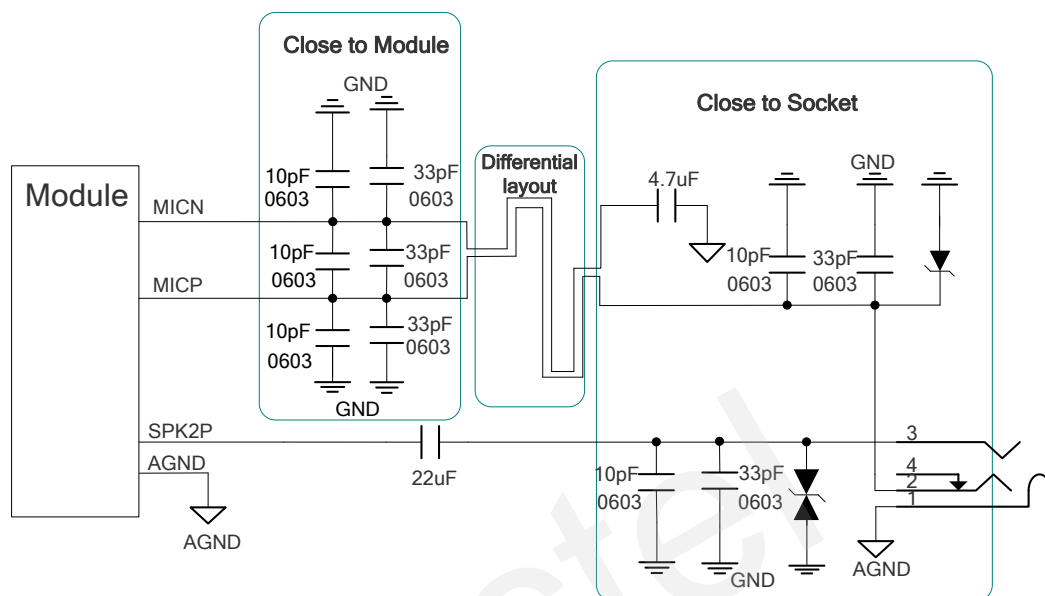


Figure 27: Earphone Interface Design

3.8.5. Audio Characteristics

Table 10: Typical Electret Microphone Characteristics

Parameter	Min.	Typ.	Max.	Unit
Working Voltage	1.2	1.5	2.0	V
Working Current	200		500	uA
External Microphone Load Resistance		2.2		k Ohm

Table 11: Typical Speaker Characteristics

Parameter	Min.	Typ.	Max.	Unit
AOUT1 Output	Single-ended	Load resistance	32	Ohm
		Ref level	0	2.4
	Differential	Load resistance	32	Ohm
		Ref level	0	4.8

AOUT2 Output	Single-ended	Load resistance	32	Load Resistance
		Reference level	0	Vpp

3.9. PCM Interface

M66 supports PCM interface. It is used for digital audio transmission between the module and the device. This interface is composed of PCM_CLK, PCM_SYNC, PCM_IN and PCM_OUT signal lines.

Pulse-code modulation (PCM) is a converter that changes the consecutive analog audio signal to discrete digital signal. The whole procedure of Pulse-code modulation contains sampling, quantizing and encoding.

Table 12: Pin Definition of PCM Interface

Pin NO.	Pin Name	Description
30	PCM_CLK	PCM clock output
31	PCM_SYNC	PCM frame synchronization output
32	PCM_IN	PCM data input
33	PCM_OUT	PCM data output

3.9.1. Configuration

M66 module supports 13-bit line code PCM format. The sample rate is 8 KHz, and the clock source is 256 KHz, and the module can only act as master mode. The PCM interface supports both long and short synchronization simultaneously. Furthermore, it only supports MSB first. For detailed information, please refer to the table below.

Table 13: Configuration

PCM	
Line Interface Format	Linear
Data Length	Linear: 13 bits

Sample Rate	8KHz
PCM Clock/Synchronization Source	PCM master mode: clock and synchronization is generated by module
PCM Synchronization Rate	8KHz
PCM Clock Rate	PCM master mode: 256 KHz (line)
PCM Synchronization Format	Long/short synchronization
PCM Data Ordering	MSB first
Zero Padding	Yes
Sign Extension	Yes

3.9.2. Timing

The sample rate of the PCM interface is 8 KHz and the clock source is 256 KHz, so every frame contains 32 bits data, since M66 supports 16 bits line code PCM format, the left 16 bits are invalid. The following diagram shows the timing of different combinations. The synchronization length in long synchronization format can be programmed by firmware from one bit to eight bits. In the Sign extension mode, the high three bits of 16 bits are sign extension, and in the Zero padding mode, the low three bits of 16 bits are zero padding.

Under zero padding mode, you can configure the PCM input and output volume by executing **AT+QPCMVOL** command. For more details, please refer to **Chapter 3.9.4**.

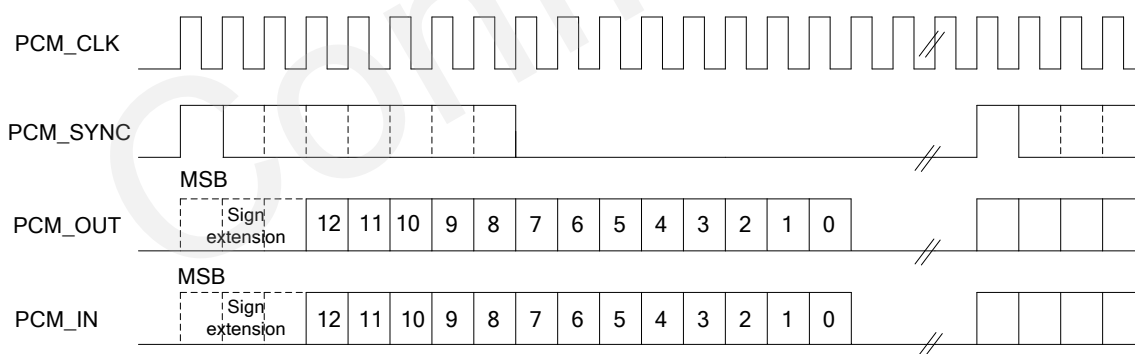


Figure 28: Long Synchronization & Sign Extension Diagram

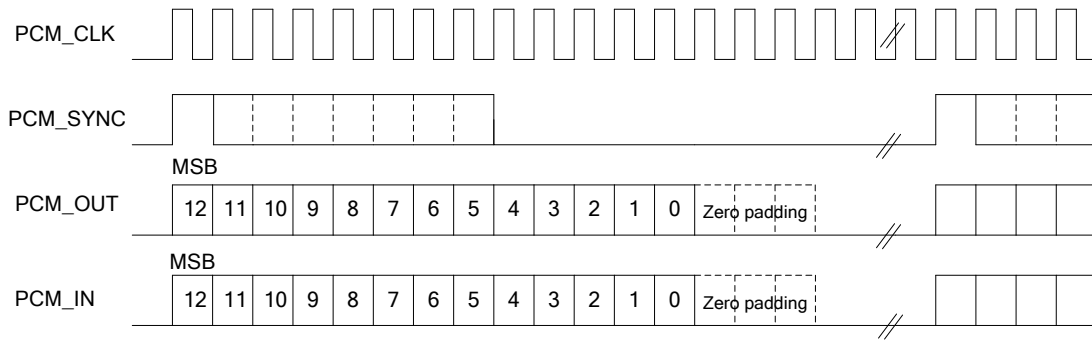


Figure 29: Long Synchronization & Zero Padding Diagram

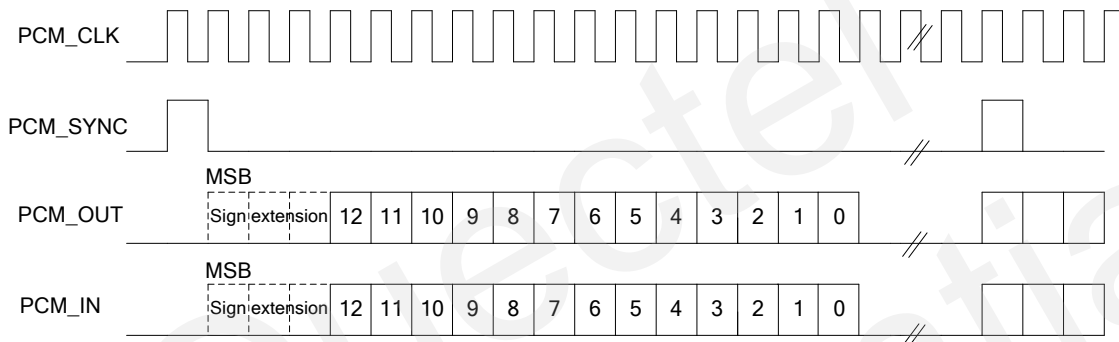


Figure 30: Short Synchronization & Sign Extension Diagram

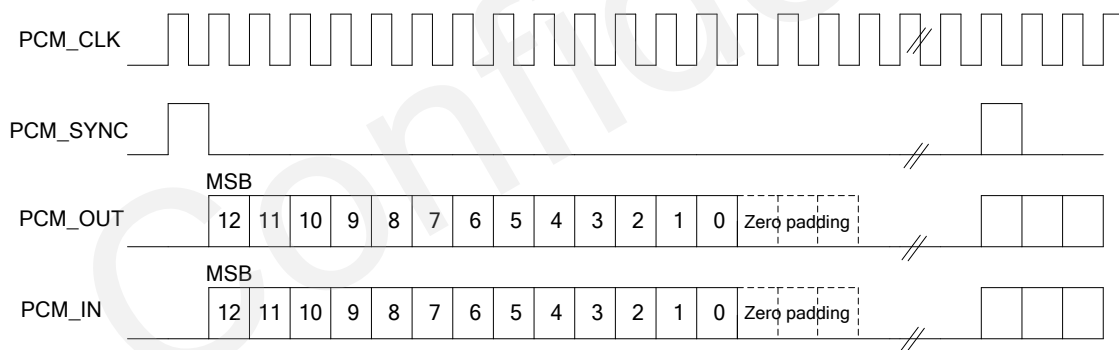


Figure 31: Short Synchronization & Zero Padding Diagram

3.9.3. Reference Design

M66 can only work as a master, providing synchronization and clock source. The reference design is shown as below.

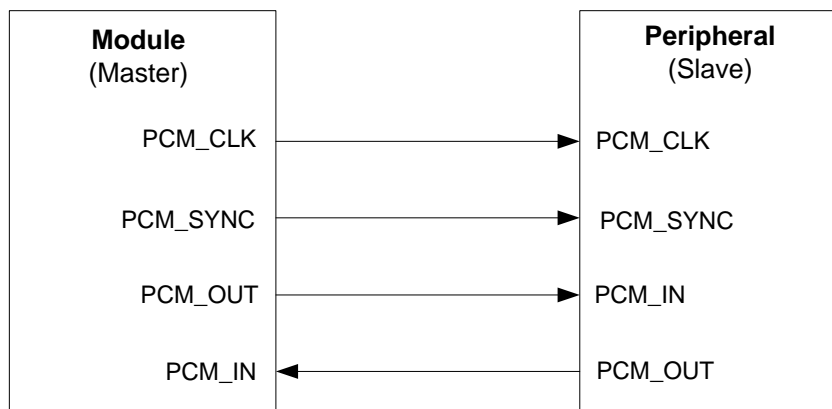


Figure 32: Reference Design for PCM

3.9.4. AT Command

There are two AT commands about the configuration of PCM, listed as below.

AT+QPCMON can configure operating mode of PCM.

AT+QPCMON=mode, Sync_Type, Sync_Length, SignExtension, MSBFirst.

Table 14: QPCMON Command Description

Parameter	Scope	Description
Mode	0~2	0: Close PCM 1: Open PCM 2: Open PCM when audio talk is set up
Sync_Type	0~1	0: Short synchronization 1: Long synchronization
Sync_Length	1~8	Programmed from one bit to eight bit
SignExtension	0~1	0: Zero padding 1: Sign extension
MSBFirst	0~1	0: MSB first 1: Not support

AT+QPCMVOL can configure the volume of input and output.

AT+QPCMVOL=vol_pcm_in, vol_pcm_out

Table 15: QPCMVOL Command Description

Parameter	Scope	Description
vol_pcm_in	0~32767	Set the input volume
vol_pcm_out	0~32767	Set the output volume The voice may be distorted when this value exceeds 16384.

3.10. SIM Card Interface

3.10.1. SIM Card Application

The SIM interface supports the functionality of the GSM Phase 1 specification and also supports the functionality of the new GSM Phase 2+ specification for FAST 64 kbps SIM card, which is intended for use with a SIM application Tool-kit.

The SIM interface is powered by an internal regulator in the module. Both 1.8V and 3.0V SIM Cards are supported.

Table 16: Pin Definition of the SIM Interface

Pin NO.	Name	Description
14	SIM_VDD	Supply power for SIM card. Automatic detection of SIM card voltage. 3.0V±5% and 1.8V±5%. Maximum supply current is around 10mA.
13	SIM_CLK	SIM card clock.
11	SIM_DATA	SIM card data I/O.
12	SIM_RST	SIM card reset.
10	SIM_GND	SIM card ground.

The reference circuit for a 6-pin SIM card socket is illustrated as the following figure.

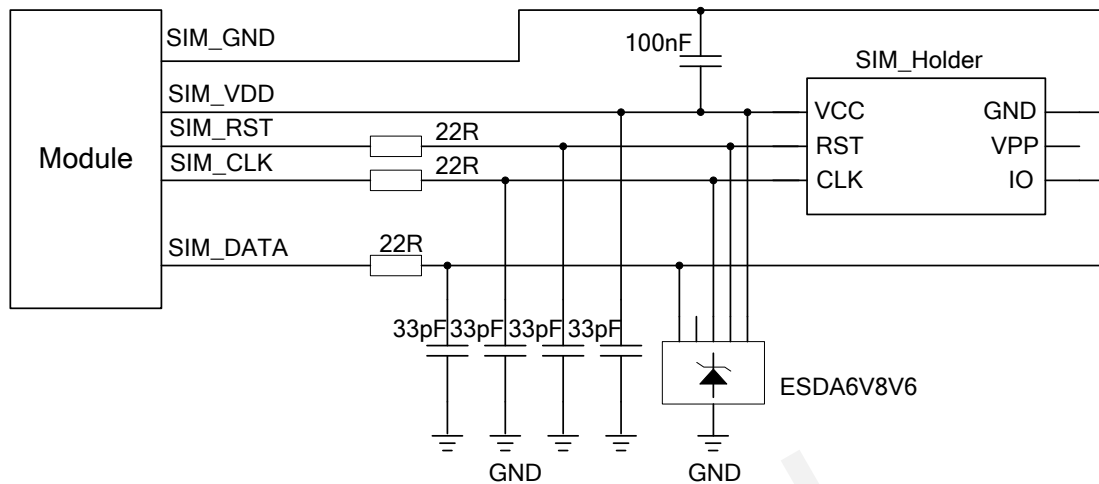


Figure 33: Reference Circuit for SIM Interface with the 6-pin SIM Card Holder

In order to enhance the reliability and availability of the SIM card in application. Please follow the below criteria in the SIM circuit design:

- Keep layout of SIM card as close as possible to the module. Assure the possibility of the length of the trace is less than 200mm.
- Keep SIM card signal away from RF and VBAT alignment.
- Assure the ground between module and SIM cassette short and wide. Keep the width of ground no less than 0.5mm to maintain the same electric potential. The decouple capacitor of SIM_VDD is less than 1uF and must be near to SIM cassette.
- To avoid cross talk between SIM_DATA and SIM_CLK. Keep them away with each other and shield them with surrounded ground
- In order to offer good ESD protection, it is recommended to add TVS such as WILL (<http://www.willsemi.com>) ESDA6V8AV6. The 22Ω resistors should be added in series between the module and the SIM card so as to suppress the EMI spurious transmission and enhance the ESD protection. Please to be noted that the SIM peripheral circuit should be close to the SIM card socket.
- Place the RF bypass capacitors (33pF) close to the SIM card on all signals line for improving EMI.

3.10.2. 6-Pin SIM Cassette

As to the 6-pin SIM card holder, it is recommended to use Amphenol C707 10M006 512 2. Please visit <http://www.amphenol.com> for more information.

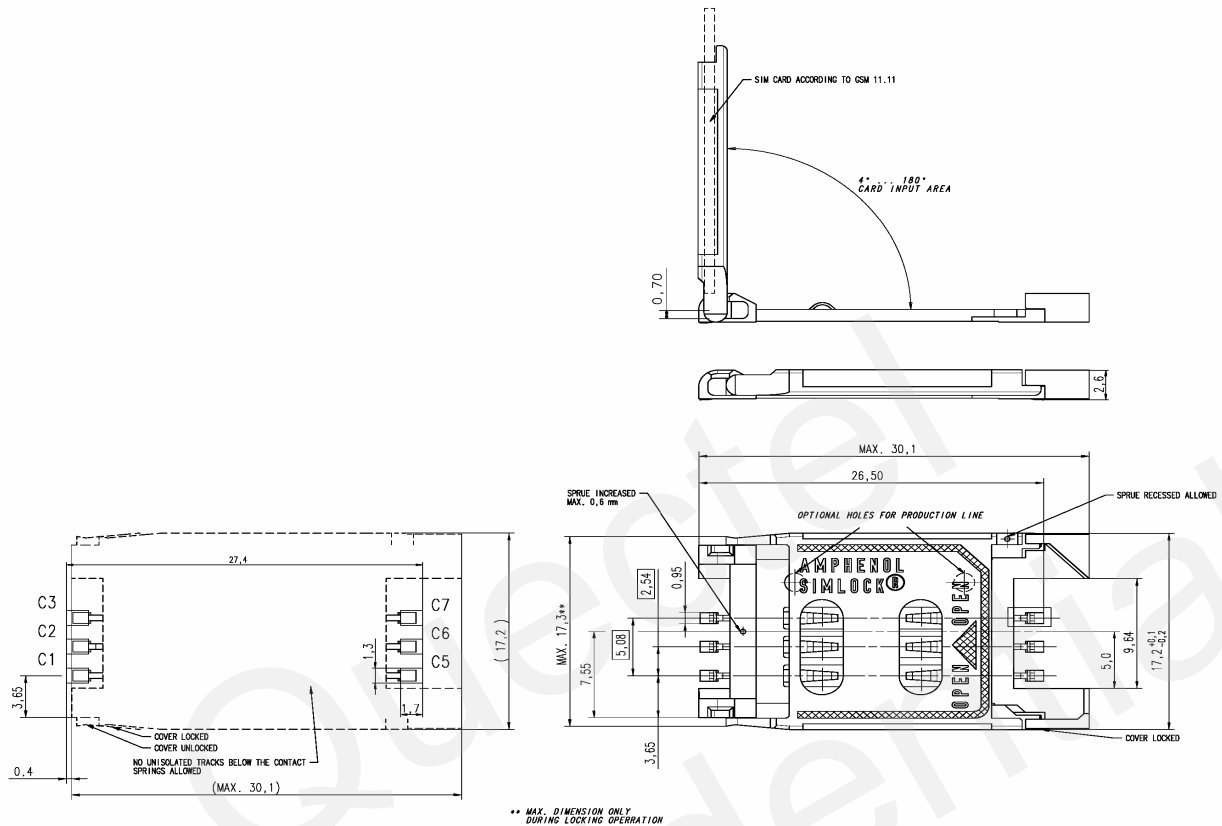


Figure 34: Amphenol C707 10M006 512 2 SIM Card Holder

Table 17: Pin Description of Amphenol SIM Card Holder

Name	Pin	Description
SIM_VDD	C1	SIM card power supply
SIM_RST	C2	SIM card reset
SIM_CLK	C3	SIM card clock
GND	C5	Ground
VPP	C6	Not connected
SIM_DATA	C7	SIM card data I/O

3.11. ADC

The module provides an ADC channel to measure the value of voltage. Please give priority to the use of ADC0 channel. The command **AT+QADC** can read the voltage value applied on ADC0 pin. For details of this AT command, please refer to the **document [1]**. In order to improve the accuracy of ADC, the layout of ADC should be surrounded by ground.

Table 18: Pin Definition of the ADC

Pin NO.	Pin Name	Description
8	AVDD	Reference voltage of ADC circuit
9	ADC0	Analog to digital converter.

Table 19: Characteristics of the ADC

Item	Min.	Typ.	Max.	Units
Voltage Range	0		2.8	V
ADC Resolution		10		bits
ADC Accuracy		2.7		mV

3.12. Behaviors of The RI

Table 20: Behaviors of the RI

State	RI Response
Standby	HIGH
Voicecall	Change to LOW, then: <ol style="list-style-type: none"> 1. Change to HIGH when call is established. 2. Use ATH to hang up the call, RI changes to HIGH. 3. Calling part hangs up, RI changes to HIGH first, and changes to LOW for 120ms indicating "NO CARRIER" as an URC, then changes to HIGH again. 4. Change to HIGH when SMS is received.
SMS	When a new SMS comes, the RI changes to LOW and holds low level for about

120ms, then changes to HIGH.

URC

Certain URCs can trigger 120ms low level on RI. For more details, please refer to the **document [1]**

If the module is used as a caller, the RI would maintain high except the URC or SMS is received. On the other hand, when it is used as a receiver, the timing of the RI is shown below.

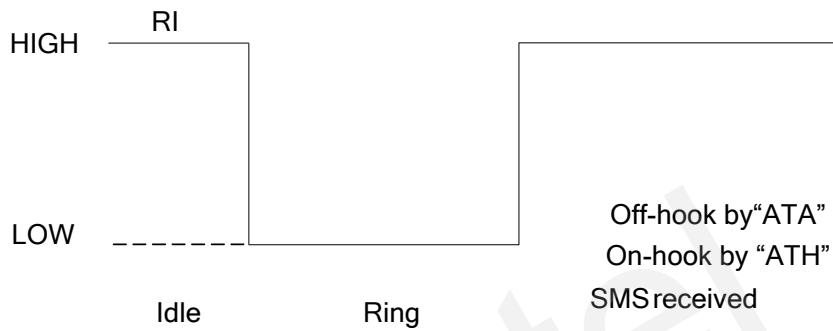


Figure 35: RI Behavior of Voice Calling as a Receiver

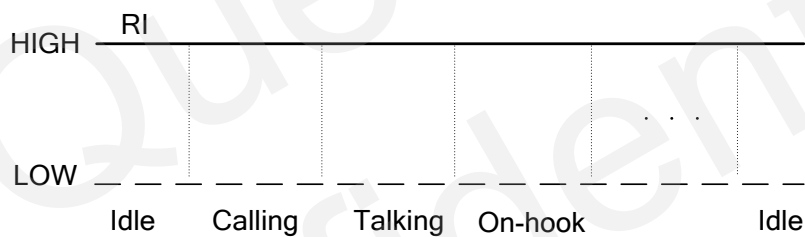


Figure 36: RI Behavior as a Caller

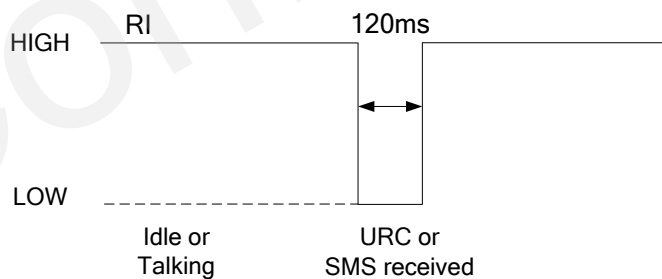


Figure 37: RI Behavior of URC or SMS Received

3.13. Network Status Indication

The NETLIGHT signal can be used to drive a network status indicator LED. The working state of this pin is listed in the following table.

Table 21: Working State of the NETLIGHT

State	Module Function
Off	The module is not running.
64ms On/800ms Off	The module is not synchronized with network.
64ms On/2000ms Off	The module is synchronized with network.
64ms On/600ms Off	The GPRS data transmission after dialing the PPP connection.

A reference circuit is shown as below.

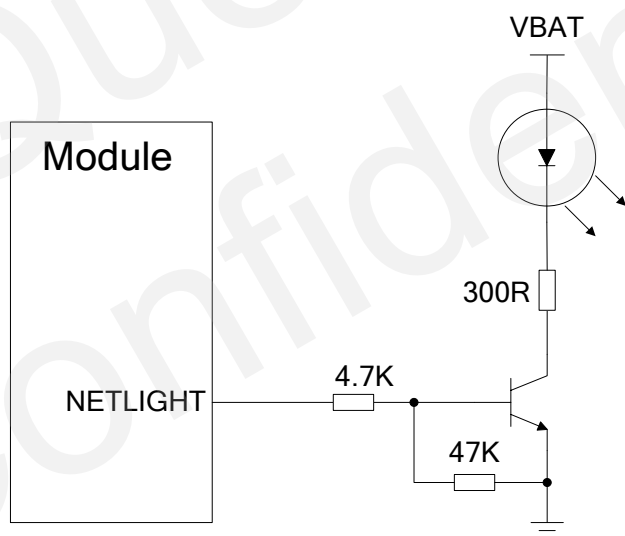


Figure 38: Reference Design for NETLIGHT

3.14. RF Transmitting Signal Indication

RFTXMON will output a high level to indicate the RF transmission, 220us later GSM will transmit burst.

Table 22: Pin Definition of the RFTXMON

Name	Pin	Description
RFTXMON	25	Transmission signal indication

You can execute **AT+QCFG="RFTXburst", 1** to enable the function.

The timing of the RFTXMON signal is shown below.

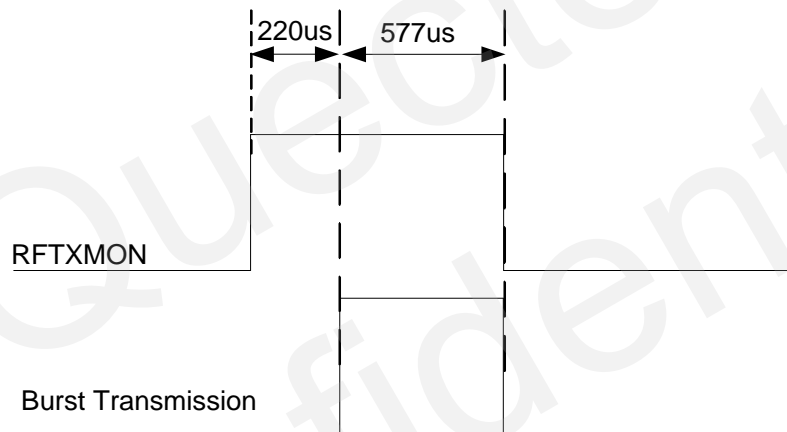


Figure 39: RFTXMON Signal during Burst Transmission

4 Antenna Interface

M66 have two antenna interfaces, GSM antenna and BT antenna. The Pin 26 is the Bluetooth antenna pad. The Pin 35 is the GSM antenna pad. The RF interface of the two antenna pad has an impedance of 50Ω.

4.1. GSM Antenna Interface

There is a GSM antenna pad named RF_ANT for M66.

Table 23: Pin Definition of the RF_ANT

Name	Pin	Description
GND	34	Ground
RF_ANT	35	GSM antenna pad
GND	36	Ground
GND	37	Ground

4.1.1. Reference Design

The external antenna must be matched properly to achieve best performance, so the matching circuit is necessary, the reference design for RF is shown as below.

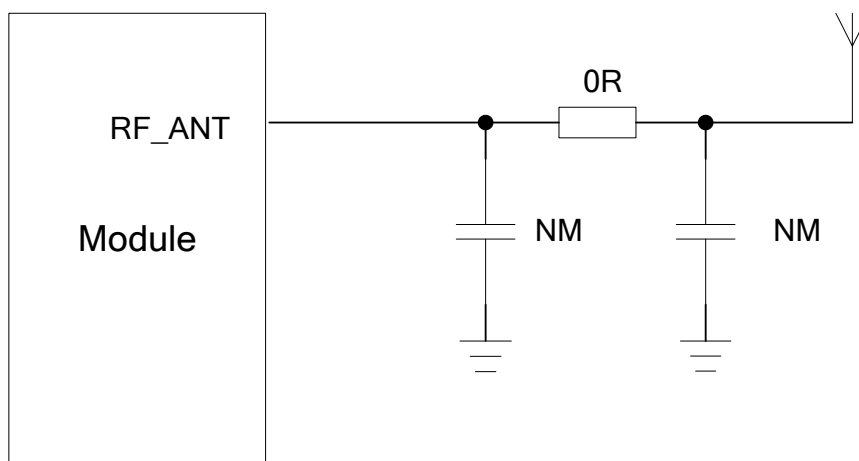


Figure 40: Reference Design for GSM Antenna

M66 provides an RF antenna pad for antenna connection. The RF trace in host PCB connected to the module RF antenna pad should be coplanar waveguide line or microstrip line, whose characteristic impedance should be close to 50Ω. M66 comes with grounding pads which are next to the antenna pad in order to give a better grounding. Besides, a π type match circuit is suggested to be used to adjust the RF performance.

To minimize the loss on the RF trace and RF cable, take design into account carefully. The following table shows the requirement on GSM antenna.

Table 24: Antenna Cable Requirements

Type	Requirements
GSM850/EGSM900	Cable insertion loss <1dB
DCS1800/PCS1900	Cable insertion loss <1.5dB

Table 25: Antenna Requirements

Type	Requirements
Frequency Range	Depending by frequency band (s) provided by the network operator
VSWR	≤ 2
Gain (dBi)	3
Max Input Power (W)	50

Input Impedance (Ω)	50
Polarization Type	Vertical

4.1.2. RF Output Power

Table 26: The Module Conducted RF Output Power

Frequency	Max.	Min.
GSM850	33dBm \pm 2dB	5dBm \pm 5dB
EGSM900	33dBm \pm 2dB	5dBm \pm 5dB
DCS1800	30dBm \pm 2dB	0dBm \pm 5dB
PCS1900	30dBm \pm 2dB	0dBm \pm 5dB

NOTE

In GPRS 4 slots TX mode, the max output power is reduced by 2.5dB. This design conforms to the GSM specification as described in section **13.16** of **3GPP TS 51.010-1**.

4.1.3. RF Receiving Sensitivity

Table 27: The Module Conducted RF Receiving Sensitivity

Frequency	Receive Sensitivity
GSM850	< -109dBm
EGSM900	< -109dBm
DCS1800	< -109dBm
PCS1900	< -109dBm

4.1.4. Operating Frequencies

Table 28: The Module Operating Frequencies

Frequency	Receive	Transmit	ARFCH
GSM850	869~894MHz	824~849MHz	128~251
EGSM900	925~960MHz	880~915MHz	0~124, 975~1023
DCS1800	1805~1880MHz	1710~1785MHz	512~885
PCS1900	1930~1990MHz	1850~1910MHz	512~810

4.1.5. RF Cable Soldering

Soldering the RF cable to RF pad of module correctly will reduce the loss on the path of RF, please refer to the following example of RF soldering.

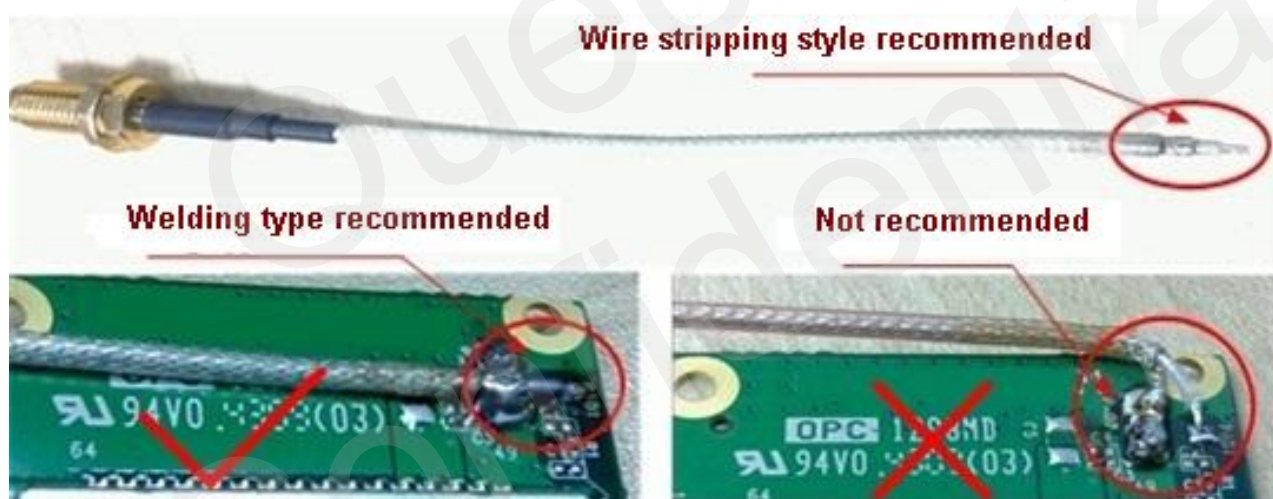


Figure 41: RF Soldering Sample

4.2. Bluetooth Antenna Interface

M66 supports Bluetooth interface. Bluetooth is a wireless technology that allows devices to communicate, or transmit data or voice, wirelessly over a short distance. It is described as a short-range communication technology intended to replace the cables connecting portable and/or fixed devices while maintaining high level of security. Bluetooth is standardized as IEEE802.15 and operates in the 2.4 GHz range using RF technology. Its bandwidth is 1Mb/s.

M66 is fully compliant with Bluetooth specification 3.0. M66 supports profile including SPP, OPP and HFP.

The module provides a Bluetooth antenna pad named BT_ANT.

Table 29: Pin Definition of the BT_ANT

Name	Pin	Description
BT_ANT	26	BT antenna pad
GND	27	Ground

The external antenna must be matched properly to achieve best performance, so the matching circuit is necessary, the connection is recommended as in the following figure:

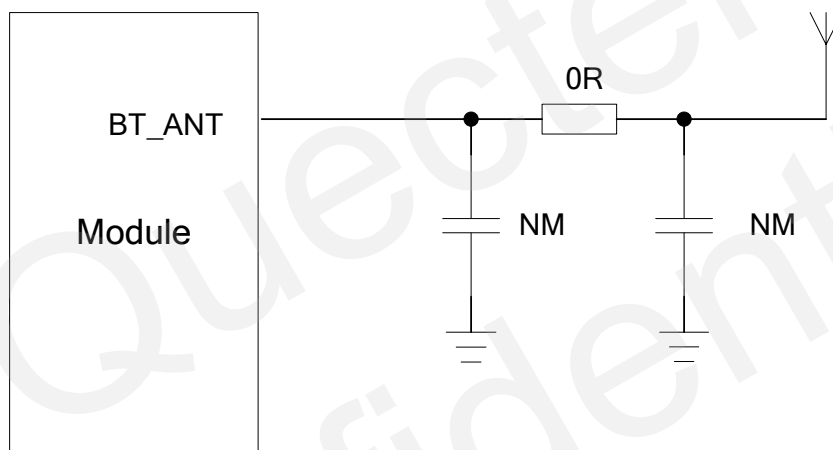


Figure 42: Reference Design for Bluetooth Antenna

There are some suggestions for placing components and RF trace lying for Bluetooth RF traces:

- Antenna matching circuit should be closed to the antenna;
- Keep the RF traces as 50Ω;
- The RF traces should be kept far away from the high frequency signals and strong disturbing source.

5 Electrical, Reliability and Radio Characteristics

5.1. Absolute Maximum Ratings

Absolute maximum ratings for power supply and voltage on digital and analog pins of module are listed in the following table:

Table 30: Absolute Maximum Ratings

Parameter	Min.	Max.	Unit
V _{BAT}	-0.3	+4.73	V
Peak Current of Power Supply	0	2	A
RMS Current of Power Supply (during one TDMA- frame)	0	0.7	A
Voltage at Digital Pins	-0.3	3.08	V
Voltage at Analog Pins	-0.3	3.08	V
Voltage at Digital/analog Pins in Power Down Mode	-0.25	0.25	V

5.2. Operating Temperature

The operating temperature is listed in the following table:

Table 31: Operating Temperature

Parameter	Min.	Typ.	Max.	Unit
Normal Temperature	-35	+25	+80	°C

Restricted Operation ¹⁾	-40 ~ -35	+80 ~ +85	°C
Storage Temperature	-45	+90	°C

NOTE

¹⁾ When the module works within this temperature range, the deviation from the GSM specification may occur. For example, the frequency error or the phase error will be increased.

5.3. Power Supply Ratings

Table 32: The Module Power Supply Ratings

Parameter	Description	Conditions	Min.	Typ.	Max.	Unit	
VBAT	Supply voltage	Voltage must stay within the min/max values, including voltage drop, ripple, and spikes.	3.3	4.0	4.6	V	
	Voltage drop during transmitting burst	Maximum power control level on GSM850 and GSM900.			400	mV	
I _{VBAT}	Average supply current	Power down mode		150		µA	
		SLEEP mode @DRX=5		1.3		mA	
		Minimum functionality mode AT+CFUN=0					
		IDLE mode			13		mA
		SLEEP mode			0.98		mA
		AT+CFUN=4					
		IDLE mode			13		mA
		SLEEP mode			1.0		mA
		TALK mode GSM850/EGSM 900 ¹⁾			195/204		mA
		DCS1800/PCS1900 ²⁾			129/145		mA
DATA mode, GPRS (3Rx, 2Tx)	GSM850/EGSM 900 ¹⁾			340/355		mA	
	DCS1800/PCS1900 ²⁾			214/262		mA	
DATA mode, GPRS (2 Rx,3Tx)	GSM850/EGSM 900 ¹⁾			485/512		mA	
	DCS1800/PCS1900 ²⁾			298/369		mA	
DATA mode, GPRS (4 Rx,1Tx)	GSM850/EGSM 900 ¹⁾			190/192		mA	

	DCS1800/PCS1900 ²⁾	122/146	mA
	DATA mode, GPRS (1Rx,4Tx) GSM850/EGSM 900 ¹⁾ DCS1800/PCS1900 ²⁾	465/474 ³⁾ 372/465	mA mA
Peak supply current (during transmission slot)	Maximum power control level on GSM850 and GSM900.	1.6	2 A

NOTE

- 1) ¹⁾ Power control level PCL 5.
- 2) ²⁾ Power control level PCL 0.
- 3) ³⁾ Under the GSM850 and EGSM900 spectrum, the power of 1Rx and 4Tx has been reduced.

5.4. Current Consumption

The values of current consumption are shown as below.

Table 33: The Module Current Consumption

Condition	Current Consumption
Voice Call	
GSM850	@power level #5 <250mA, Typical 195mA @power level #12, Typical 81mA @power level #19, Typical 62mA
GSM900	@power level #5 <250mA, Typical 204mA @power level #12, Typical 83mA @power level #19, Typical 62mA
DCS1800	@power level #0 <200mA, Typical 129mA @power level #7, Typical 71mA @power level #15, Typical 59mA
PCS1900	@power level #0 <200mA, Typical 145mA @power level #7, Typical 74mA @power level #15, Typical 60mA
GPRS Data	

DATA Mode, GPRS (3Rx, 2Tx) CLASS12

GSM850 @power level #5 <500mA, Typical 340mA

EGSM900 @power level #5 <500mA, Typical 355mA

DCS1800 @power level #0 <400mA, Typical 214mA

PCS1900 @power level #0 <400mA, Typical 262mA

DATA Mode, GPRS (2Rx, 3Tx) CLASS12

GSM850 @power level #5 <600mA, Typical 485mA

EGSM900 @power level #5 <600mA, Typical 512mA

DCS1800 @power level #0 <490mA, Typical 298mA

PCS1900 @power level #0 <490mA, Typical 369mA

DATA Mode, GPRS (4Rx,1Tx) CLASS12

GSM850 @power level #5 <350mA, Typical 190mA

EGSM900 @power level #5 <350mA, Typical 192mA

DCS1800 @power level #0 <300mA, Typical 122mA

PCS1900 @power level #0 <300mA, Typical 146mA

DATA Mode, GPRS (1Rx, 4Tx) CLASS12

GSM850 @power level #5 <660mA, Typical 465mA

EGSM900 @power level #5 <660mA, Typical 474mA

DCS1800 @power level #0 <530mA, Typical 372mA

PCS1900 @power level #0 <530mA, Typical 465mA

NOTE

GPRS Class 12 is the default setting. The module can be configured from GPRS Class 1 to Class 12. Setting to lower GPRS class would make it easier to design the power supply for the module.

5.5. Electro-static Discharge

Although the GSM engine is generally protected against Electro-static Discharge (ESD), ESD protection precautions should still be emphasized. Proper ESD handling and packaging procedures must be applied throughout the processing, handling and operation of any applications using the module.

The measured ESD values of module are shown as the following table:

Table 34: The ESD Endurance (Temperature: 25°C, Humidity: 45%)

Tested Point	Contact Discharge	Air Discharge
VBAT, GND	±5KV	±10KV
RF_ANT	±5KV	±10KV
TXD, RXD	±2KV	±4KV
Others	±0.5KV	±1KV

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Confidential

6 Mechanical Dimensions

This chapter describes the mechanical dimensions of the module.

6.1. Mechanical Dimensions of Module

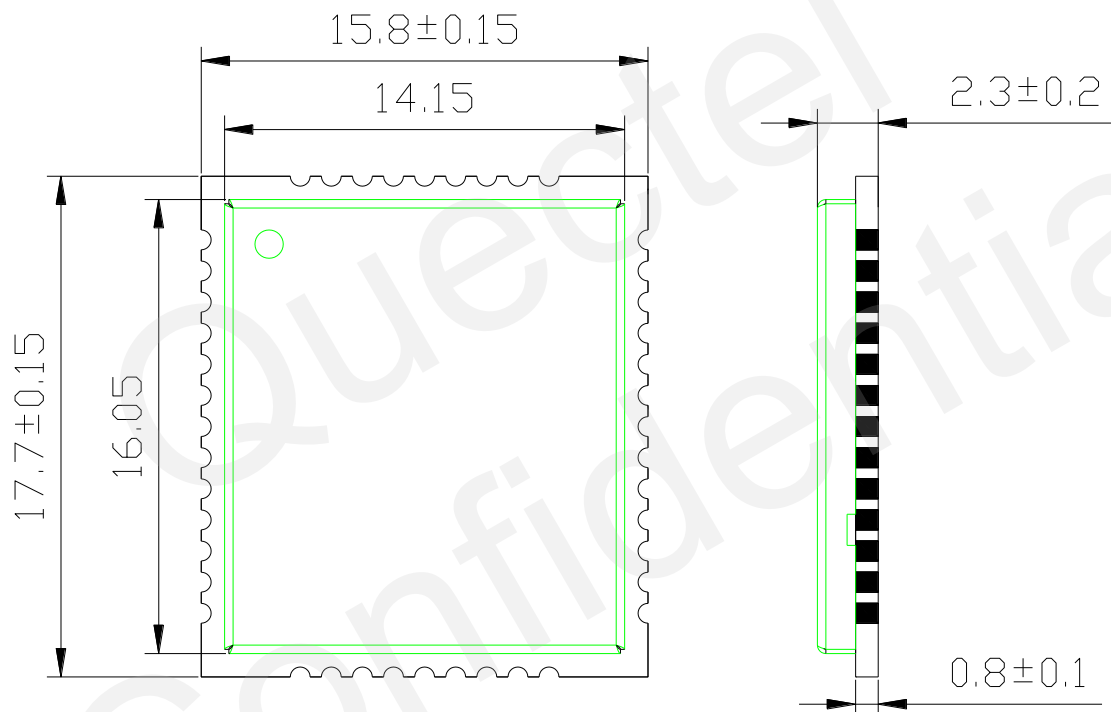


Figure 43: M66 Module Top and Side Dimensions (Unit: mm)

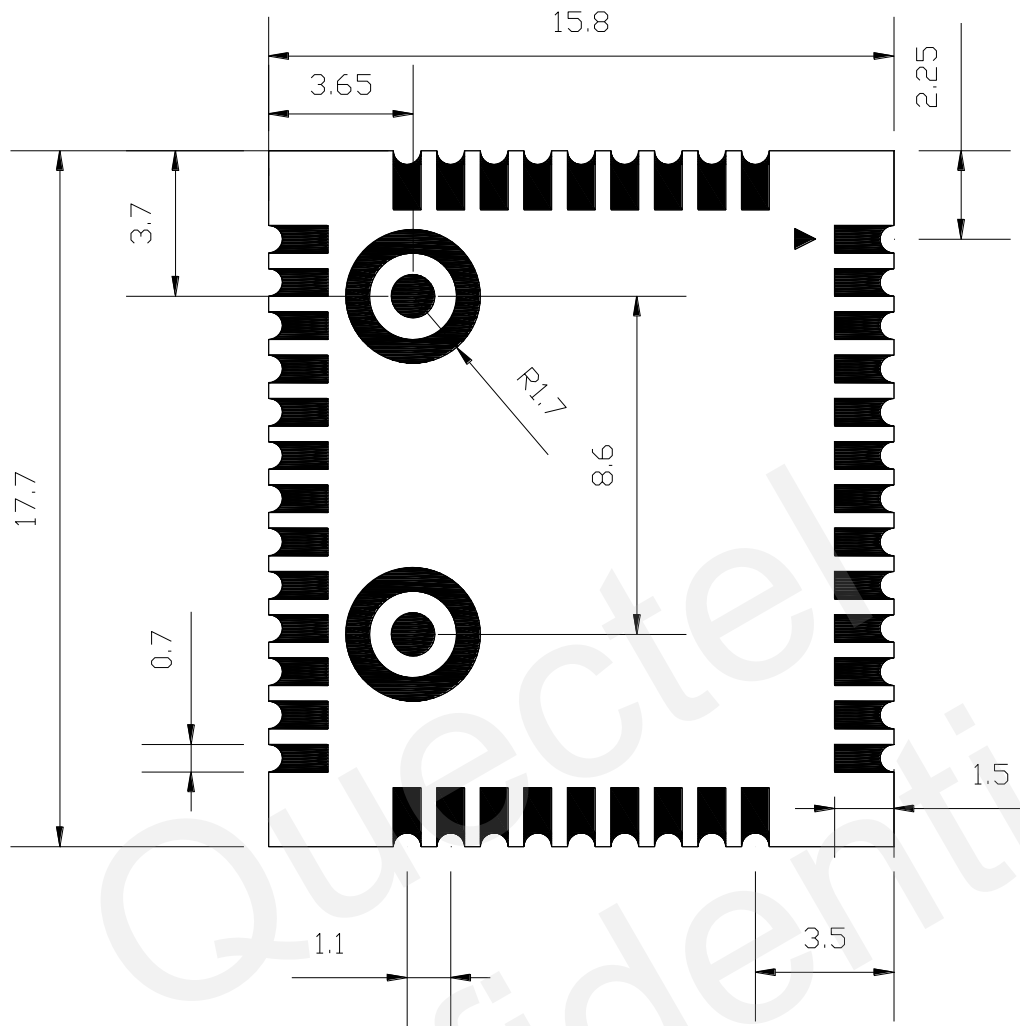


Figure 44: M66 Module Bottom Dimensions (Unit: mm)

6.2. Recommended Footprint

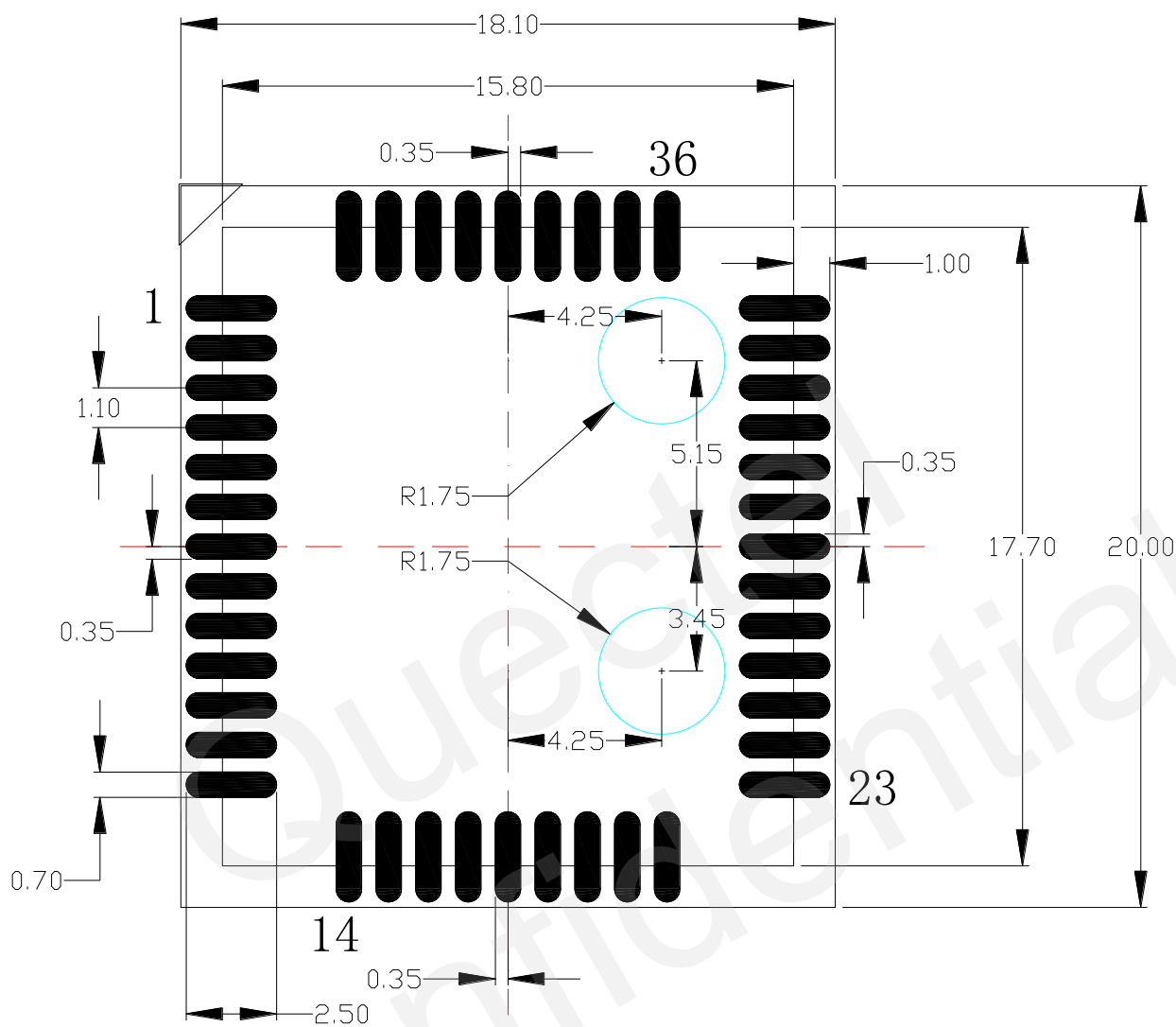


Figure 45: Recommended Footprint (Unit: mm)

NOTE

The module should keep about 3mm away from other components in the host PCB.

6.3. Top View of the Module



Figure 46: Top View of the Module

6.4. Bottom View of the Module

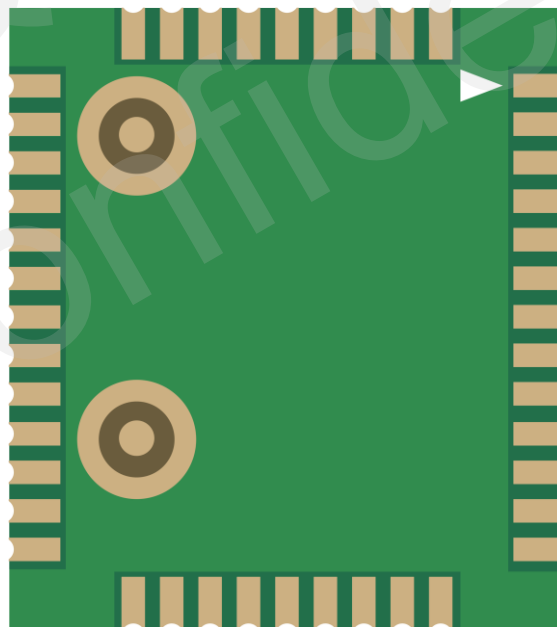


Figure 47: Bottom View of the Module

7 Storage and Manufacturing

7.1. Storage

M66 module is distributed in a vacuum-sealed bag. The restriction for storage is shown as below.

Shelf life in the vacuum-sealed bag: 12 months at environments of $<40^{\circ}\text{C}$ temperature and $<90\% \text{RH}$.

After the vacuum-sealed bag is opened, devices that need to be mounted directly must be:

- Mounted within 72 hours at the factory environment of $\leq 30^{\circ}\text{C}$ temperature and $<60\% \text{RH}$.
- Stored at $<10\% \text{RH}$.

Devices require baking before mounting, if any circumstance below occurs.

- When the ambient temperature is $23^{\circ}\text{C} \pm 5^{\circ}\text{C}$, humidity indication card shows the humidity is $>10\%$ before opening the vacuum-sealed bag.
- If ambient temperature is $<30^{\circ}\text{C}$ and the humidity is $<60\%$, the devices have not been mounted during 72hours.
- Stored at $>10\% \text{RH}$.

If baking is required, devices should be baked for 48 hours at $125^{\circ}\text{C} \pm 5^{\circ}\text{C}$.

NOTE

As plastic container cannot be subjected to high temperature, devices must be removed prior to high temperature (125°C) bake. If shorter bake times are desired, refer to the IPC/JEDECJ-STD-033 for bake procedure.

7.2. Soldering

The squeegee should push the paste on the surface of the stencil that makes the paste fill the stencil openings and penetrate to the PCB. The force on the squeegee should be adjusted so as to produce a clean stencil surface on a single pass. To ensure the module soldering quality, the thickness of stencil at the hole of the module pads should be 0.2 mm for M66. For more details, please refer to **document [13]**

It is suggested that peak reflow temperature is from 235°C to 245°C (for SnAg3.0Cu0.5 alloy). Absolute max reflow temperature is 260°C. To avoid damage to the module when it was repeatedly heated, it is suggested that the module should be mounted after the first panel has been reflowed. The following picture is the actual diagram which we have operated.

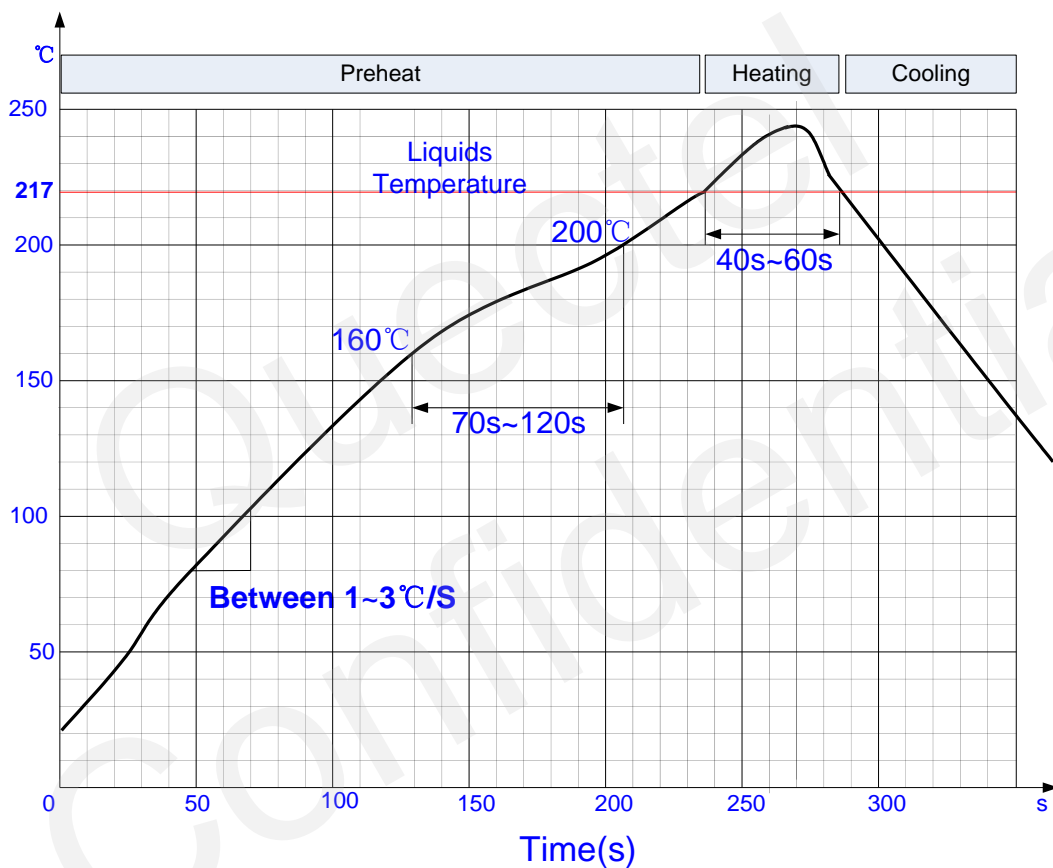


Figure 48: Ramp-Soak-Spike Reflow Profile

7.3. Packaging

The modules are stored in a vacuum-sealed bag which is ESD protected. It should not be opened until the devices are ready to be soldered onto the application.

7.3.1. Tape and Reel Packaging

The reel is 330mm in diameter and each reel contains 250 modules.

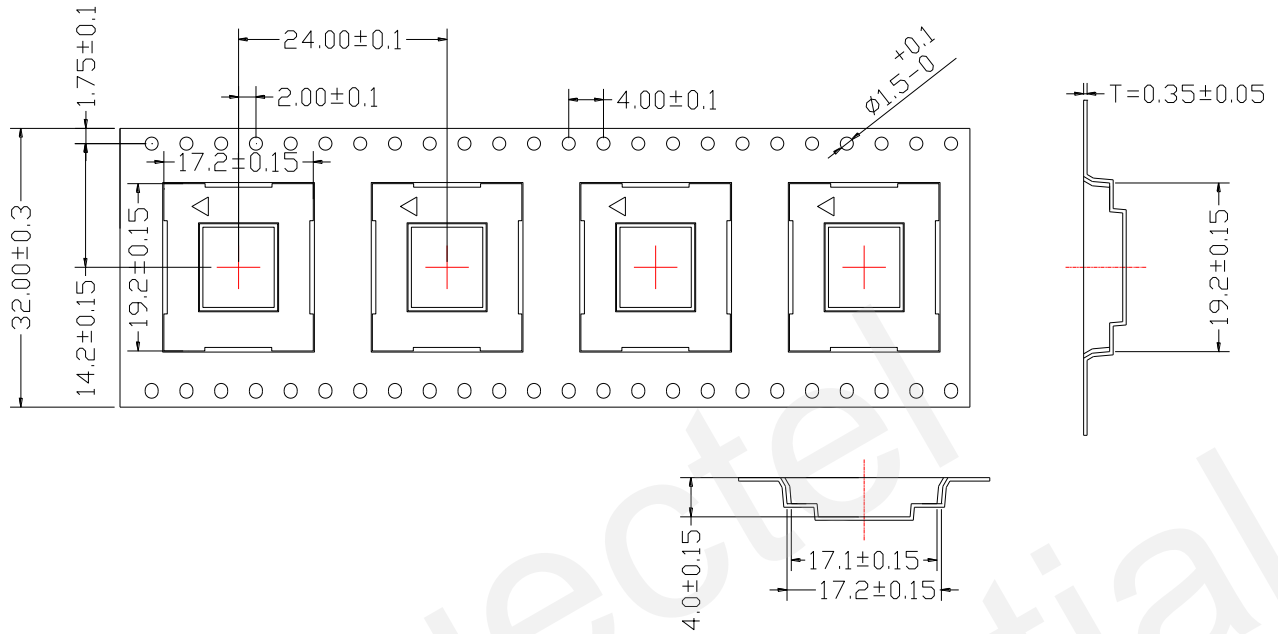


Figure 49: Tape and Reel Specification

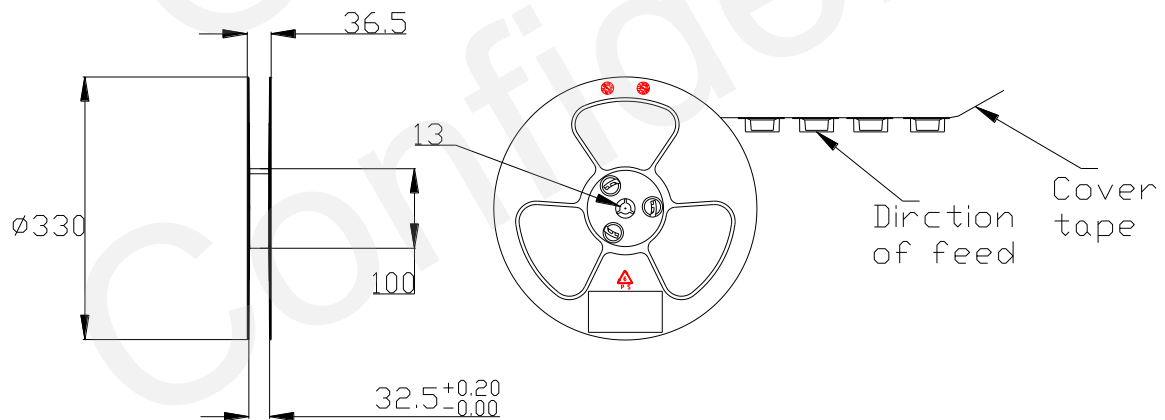


Figure 50: Dimensions of Reel

8 Appendix A Reference

Table 35: Related Documents

SN	Document Name	Remark
[1]	Quectel_M66_AT_Commands_Manual	AT commands manual
[2]	ITU-T Draft new recommendation V.25ter	Serial asynchronous automatic dialing and control
[3]	GSM 07.07	Digital cellular telecommunications (Phase 2+); AT command set for GSM Mobile Equipment (ME)
[4]	GSM 07.10	Support GSM 07.10 multiplexing protocol
[5]	GSM 07.05	Digital cellular telecommunications (Phase 2+); Use of Data Terminal Equipment – Data Circuit terminating Equipment (DTE – DCE) interface for Short Message Service (SMS) and Cell Broadcast Service (CBS)
[6]	GSM 11.14	Digital cellular telecommunications (Phase 2+); Specification of the SIM Application Toolkit for the Subscriber Identity module – Mobile Equipment (SIM – ME) interface
[7]	GSM 11.11	Digital cellular telecommunications (Phase 2+); Specification of the Subscriber Identity module – Mobile Equipment (SIM – ME) interface
[8]	GSM 03.38	Digital cellular telecommunications (Phase 2+); Alphabets and language-specific information
[9]	GSM 11.10	Digital cellular telecommunications (Phase 2); Mobile Station (MS) conformance specification; Part 1: Conformance specification
[10]	GSM_UART_Application_Note	UART port application note
[11]	GSM_FW_Upgrade_AN01	GSM Firmware upgrade application note
[12]	GSM_EVB_User_Guide	GSM EVB user guide
[13]	Module_Secondary_SMT_User_Guide	Module secondary SMT user guide

Table 36: Terms and Abbreviations

Abbreviation	Description
ADC	Analog-to-Digital Converter
AMR	Adaptive Multi-Rate
ARP	Antenna Reference Point
ASIC	Application Specific Integrated Circuit
BER	Bit Error Rate
BOM	Bill of Material
BT	Bluetooth
BTS	Base Transceiver Station
CHAP	Challenge Handshake Authentication Protocol
CS	Coding Scheme
CSD	Circuit Switched Data
CTS	Clear to Send
DAC	Digital-to-Analog Converter
DRX	Discontinuous Reception
DSP	Digital Signal Processor
DCE	Data Communications Equipment (typically module)
DTE	Data Terminal Equipment (typically computer, external controller)
DTR	Data Terminal Ready
DTX	Discontinuous Transmission
EFR	Enhanced Full Rate
EGSM	Enhanced GSM
EMC	Electromagnetic Compatibility
ESD	Electrostatic Discharge

ETS	European Telecommunication Standard
FCC	Federal Communications Commission (U.S.)
FDMA	Frequency Division Multiple Access
FR	Full Rate
GMSK	Gaussian Minimum Shift Keying
GPRS	General Packet Radio Service
GSM	Global System for Mobile Communications
G.W	Gross Weight
HR	Half Rate
I/O	Input/Output
IC	Integrated Circuit
IMEI	International Mobile Equipment Identity
I _o max	Maximum Output Load Current
kbps	Kilo Bits Per Second
LED	Light Emitting Diode
Li-Ion	Lithium-Ion
MO	Mobile Originated
MOQ	Minimum Order Quantity
MP	Manufacture Product
MS	Mobile Station (GSM engine)
MT	Mobile Terminated
N.W	Net Weight
PAP	Password Authentication Protocol
PBCCH	Packet Switched Broadcast Control Channel
PCB	Printed Circuit Board

PDU	Protocol Data Unit
PPP	Point-to-Point Protocol
RF	Radio Frequency
RMS	Root Mean Square (value)
RTC	Real Time Clock
RX	Receive Direction
SIM	Subscriber Identification Module
SMS	Short Message Service
TDMA	Time Division Multiple Access
TE	Terminal Equipment
TX	Transmitting Direction
UART	Universal Asynchronous Receiver & Transmitter
URC	Unsolicited Result Code
USSD	Unstructured Supplementary Service Data
VSWR	Voltage Standing Wave Ratio
V_{Omax}	Maximum Output Voltage Value
V_{Onorm}	Normal Output Voltage Value
V_{Omin}	Minimum Output Voltage Value
V_{IHmax}	Maximum Input High Level Voltage Value
V_{IHmin}	Minimum Input High Level Voltage Value
V_{ILmax}	Maximum Input Low Level Voltage Value
V_{ILmin}	Minimum Input Low Level Voltage Value
V_{Imax}	Absolute Maximum Input Voltage Value
V_{Inorm}	Absolute Normal Input Voltage Value
V_{imin}	Absolute Minimum Input Voltage Value

V_{OHmax} Maximum Output High Level Voltage Value

V_{OHmin} Minimum Output High Level Voltage Value

V_{OLmax} Maximum Output Low Level Voltage Value

V_{OLmin} Minimum Output Low Level Voltage Value

Phonebook Abbreviations

LD SIM Last Dialing phonebook (list of numbers most recently dialed)

MC Mobile Equipment list of unanswered MT Calls (missed calls)

ON SIM (or ME) Own Numbers (MSISDNs) list

RC Mobile Equipment list of Received Calls

SM SIM phonebook

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9 Appendix B GPRS Coding Scheme

Four coding schemes are used in GPRS protocol. The differences between them are shown in the following table.

Table 37: Description of Different Coding Schemes

Scheme	Code Rate	USF	Pre-coded USF	Radio Block excl.USF and BCS	BCS	Tail	Coded Bits	Punctured Bits	Data Rate Kb/s
CS-1	1/2	3	3	181	40	4	456	0	9.05
CS-2	2/3	3	6	268	16	4	588	132	13.4
CS-3	3/4	3	6	312	16	4	676	220	15.6
CS-4	1	3	12	428	16	-	456	-	21.4

Radio block structure of CS-1, CS-2 and CS-3 is shown as the figure below.

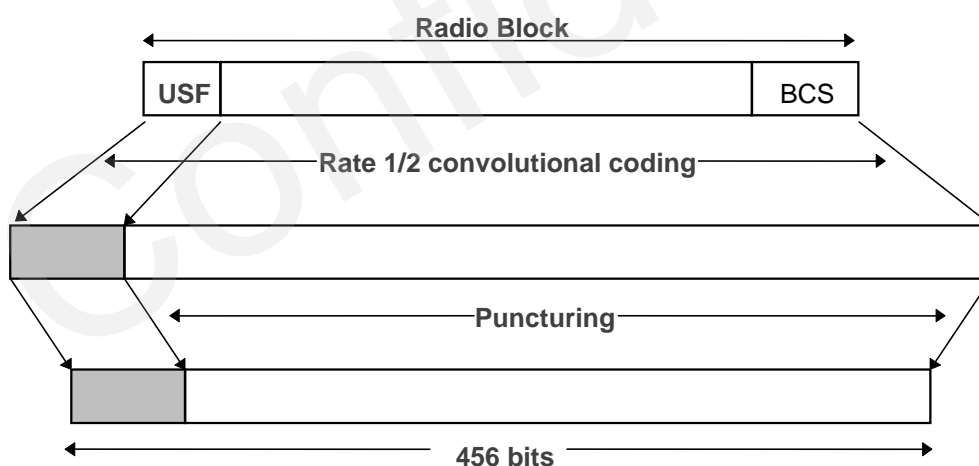


Figure 51: Radio Block Structure of CS-1, CS-2 and CS-3

Radio block structure of CS-4 is shown as the following figure.

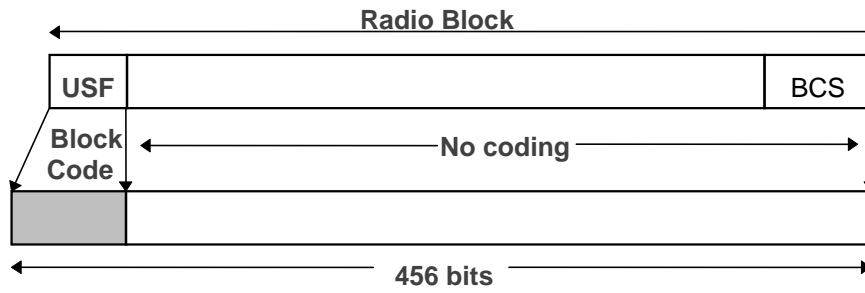


Figure 52: Radio Block Structure of CS-4

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10 Appendix C GPRS Multi-slot Class

Twenty-nine classes of GPRS multi-slot modes are defined for MS in GPRS specification. Multi-slot classes are product dependant, and determine the maximum achievable data rates in both the uplink and downlink directions. Written as 3+1 or 2+2, the first number indicates the amount of downlink timeslots, while the second number indicates the amount of uplink timeslots. The active slots determine the total number of slots the GPRS device can use simultaneously for both uplink and downlink communications. The description of different multi-slot classes is shown in the following table.

Table 38: GPRS Multi-slot Classes

Multislot Class	Downlink Slots	Uplink Slots	Active Slots
1	1	1	2
2	2	1	3
3	2	2	3
4	3	1	4
5	2	2	4
6	3	2	4
7	3	3	4
8	4	1	5
9	3	2	5
10	4	2	5
11	4	3	5
12	4	4	5